



Application Solar & ESS

Norbert Pluschke
Semikron Hong Kong

Packaging Technology in different Application



Introduction of solar & ESS

2-level & 3-level features

3-level for ESS & Solar (ANPC)

3-level Central Converter Design

3-level Commutation Difficulties

Summery

Packaging Technology in different Application



Introduction of solar & ESS

2-level & 3-level features

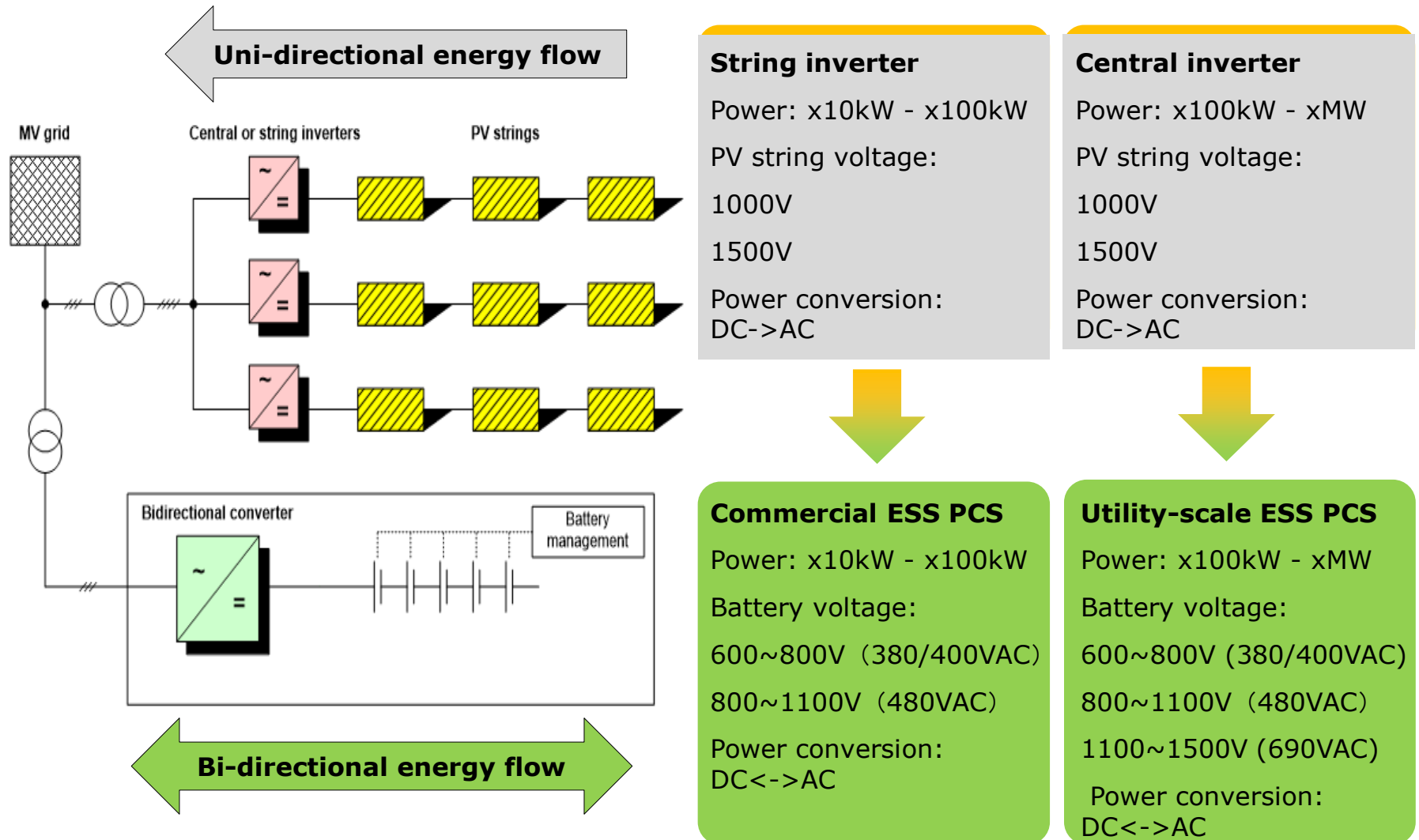
3-level for ESS & Solar (ANPC)

3-level Central Converter Design

3-level Commutation Difficulties

Summery

Introduction – Solar inverter & Energy Storage Converter



Packaging Technology in different Application



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3-level for ESS & Solar (ANPC)

3-level Central Converter Design

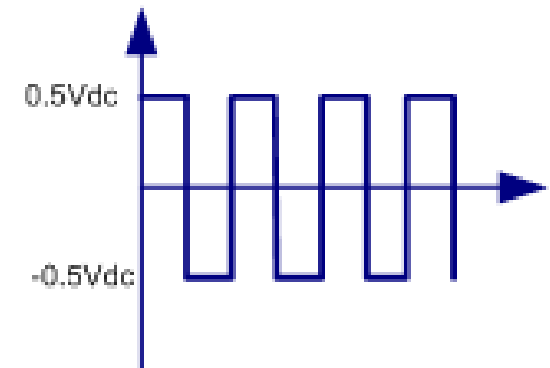
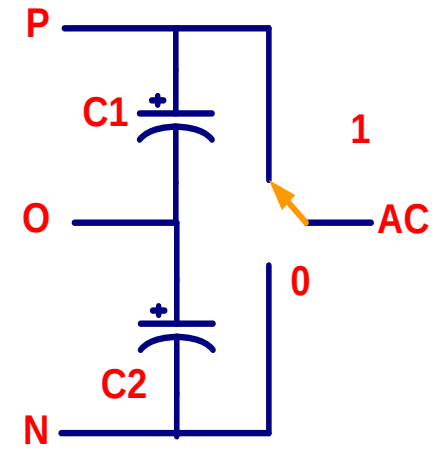
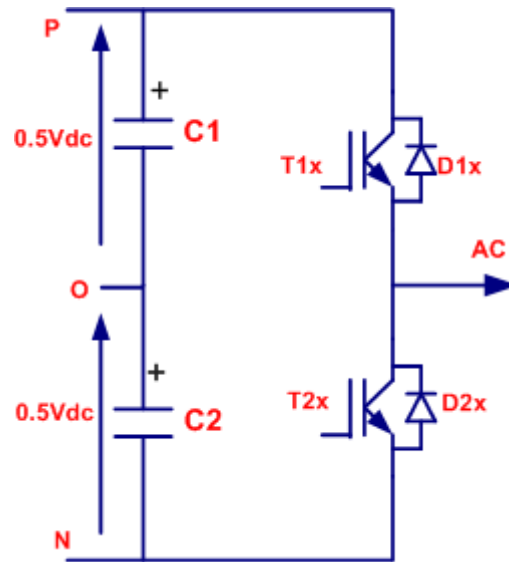
3-level Commutation Difficulties

Summery

Two Level Inverter Topology

**Output Voltage is
of Bipolar Nature**

**Only Two States
Per Phase**



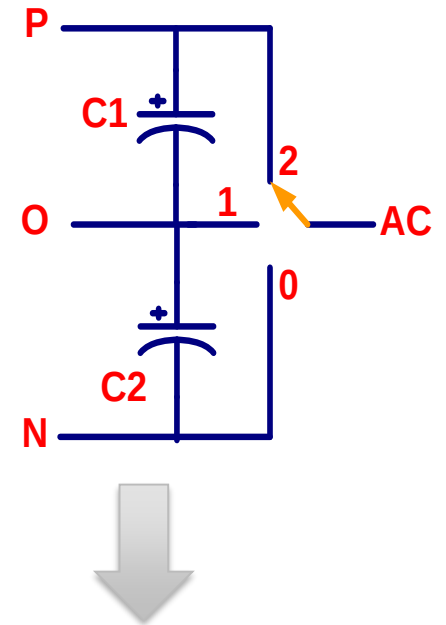
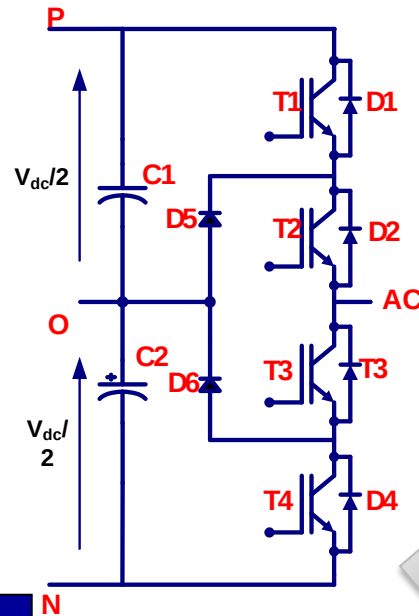
Three Level Inverter Topologies

**Output Voltage is
of Unipolar Nature**

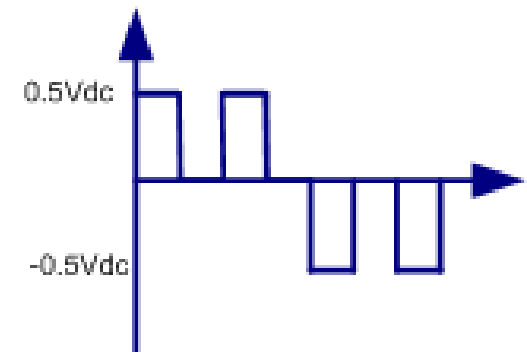
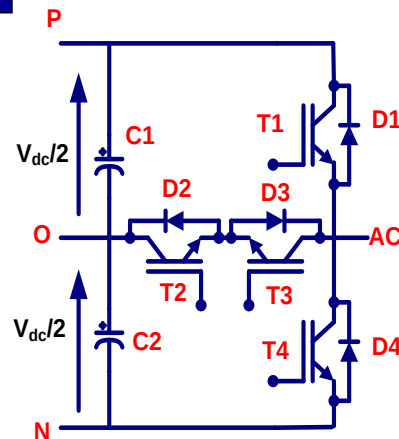
**Three States
Per Phase**

**Immediate Benefit:
Improved Output
Voltage Quality**

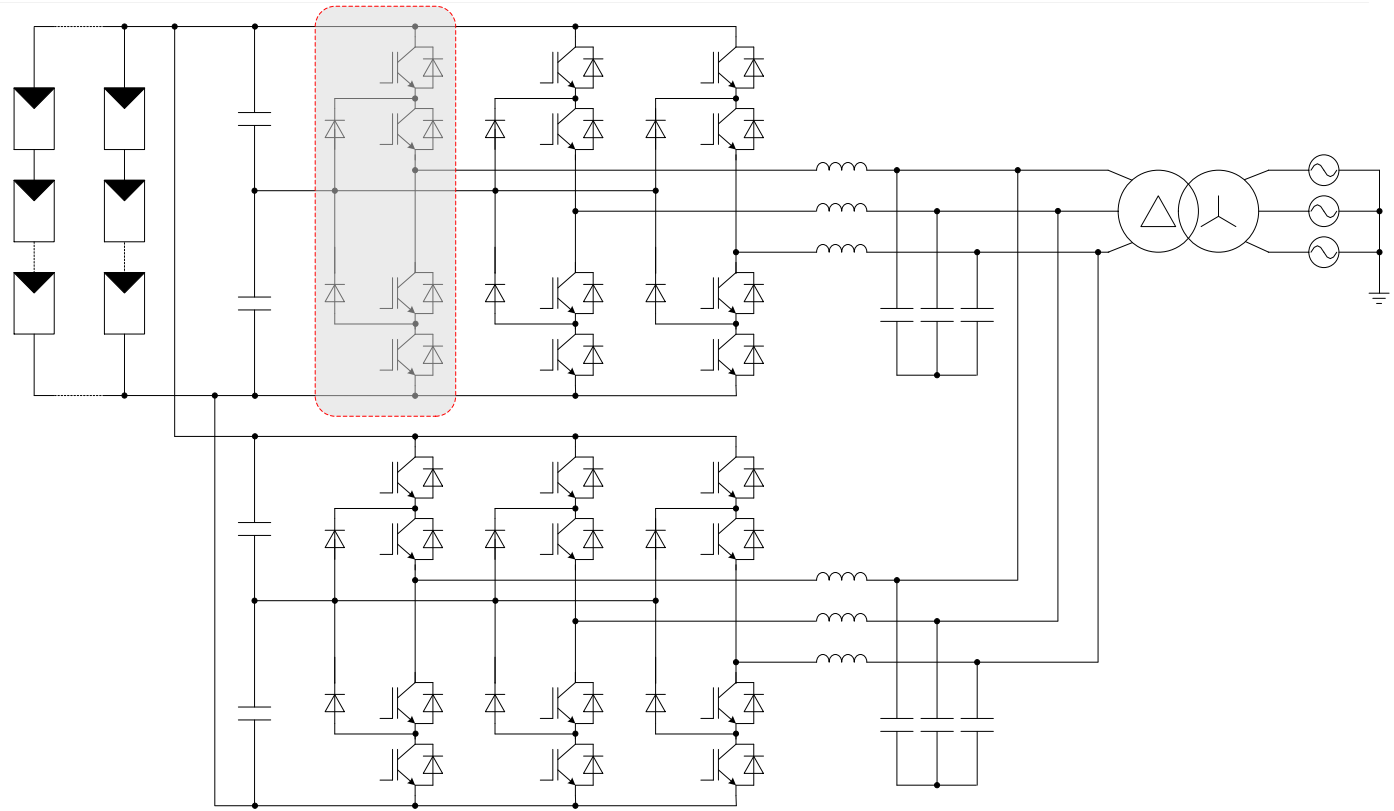
NPC



TNPC



1500V DC Solar Inverter – 3 level NPC



Module available so far

- Wish is to have all devices in one module, by today up to 300A available (MLI, TMLI) commutation is in one module
- Alternative is combination of GAL, GAR and GB module

Introduction – AC/DC topologies

String inverter

Power: x10kW - x100kW

PV string voltage:

1000V

1500V

Commercial ESS PCS

Power: x10kW - x100kW

Battery voltage:

600~800V

(380/400VAC)

800~1100V (480VAC)

Central inverter

Power: x100kW - xMW

PV string voltage:

1000V

1500V

Utility-scale ESS PCS

Power: x100kW - xMW

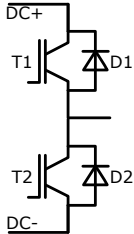
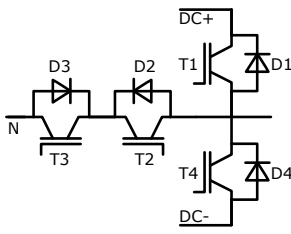
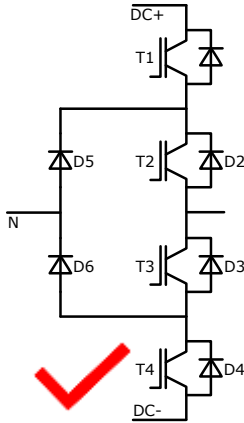
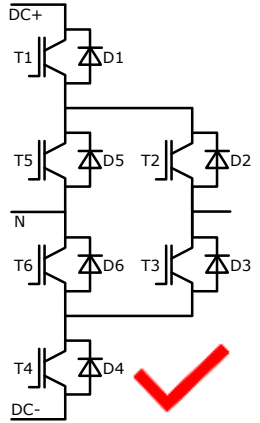
Battery voltage:

600~800V

(380/400VAC)

800~1100V (480VAC)

1100~1500V (690VAC)

Topologies	2L	TNPC 3L	NPC 3L	ANPC 3L
				
	1000V	1200V chip	1200V chip	650V chip
	1500V	1700V chip?	1700V chip?	950V, 1200V chips

Introduction – 950V chips

950V Chip				
I_{nom} [A]	100	200	200	100
Performance	Fast	Fast	Low V_{cesat}	Fast
Dimension [mm]	7 x 7	9,26 x 9,26	9,26 x 9,26	5,42 x 5,42
Area [mm ²]	49	86	86	29
V_{ce}/V_f @150°C	2,2V	2,2V	1,35V	2,15V
$E_{sw}/100A$ @150°C	10,5mJ	10,5mJ	23,5mJ	2,3mJ

Compared with 1200V T4 chip, 950V chips

- Has ~50% chip area at same I_{cnom}
- S7: E_{off} reduced ~60%, similar V_{CE}
- L7: V_{CE} reduced ~35%, E_{off} increased ~70%

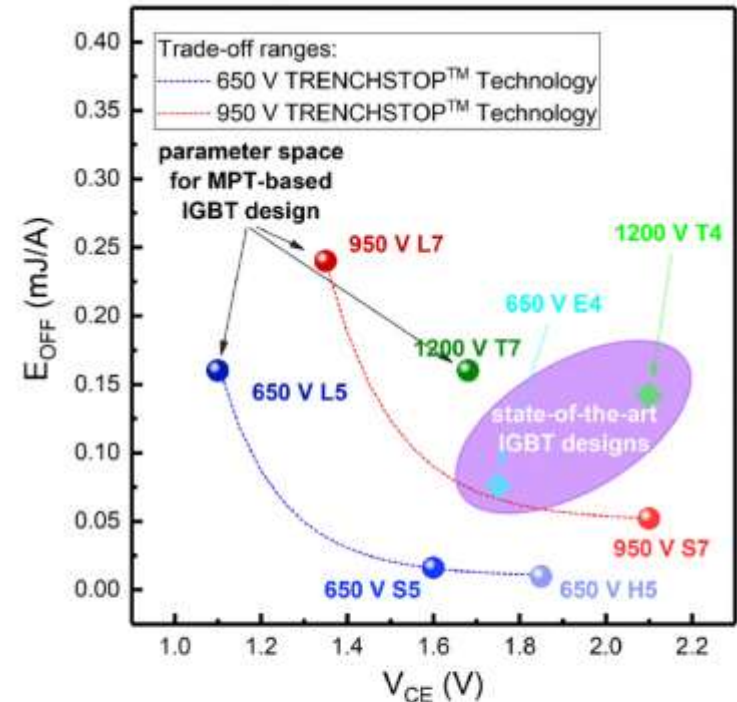
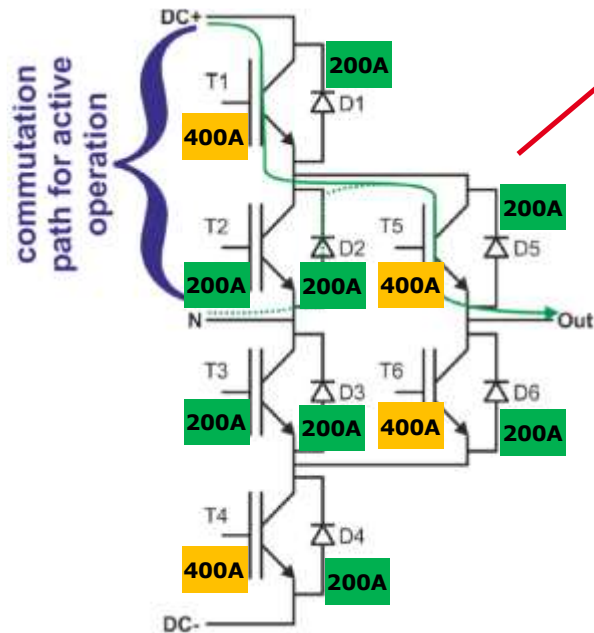


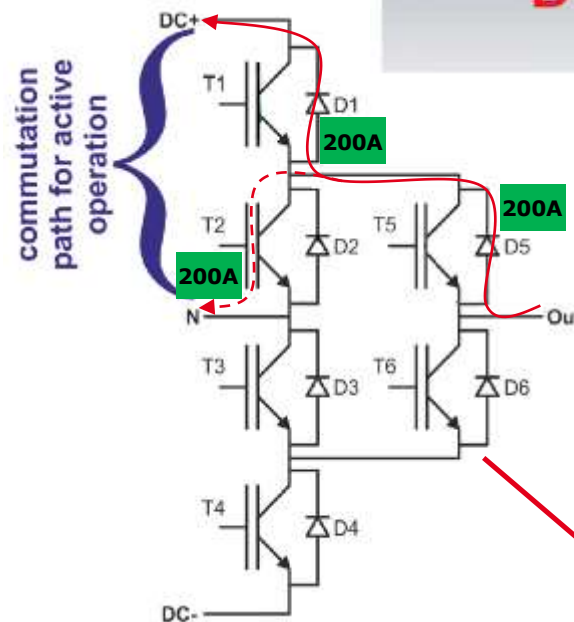
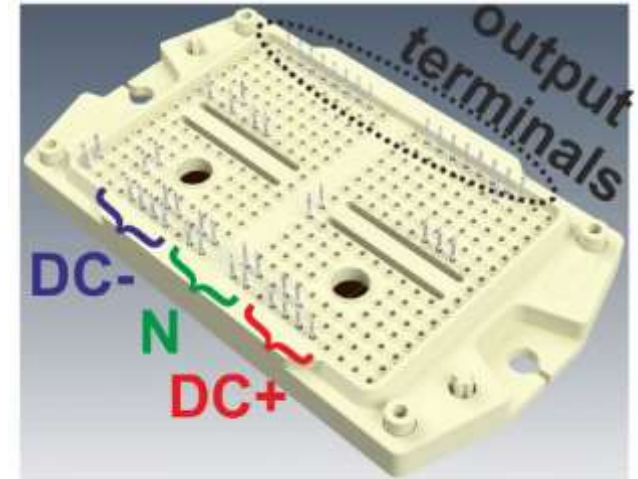
Fig. 1 Trade-off diagram of 650-V, 950-V, and 1200-V MPT IGBT technologies. Static and dynamic values are provided at $T_J = 150^\circ\text{C}$ and with $V_{DC} = 2/3 \cdot V_{CES}$. As reference, 650-V and 1200-V state-of-the-art 4th-generation IGBTs are indicated as well.

Source: Christian R. Müller, et al. "New 950-V IGBT and diode technology integrated in a low-inductive ANPC topology for solar applications", PCIM Euro, 2019

State of the art power modules for solar application - String



Designed
for solar

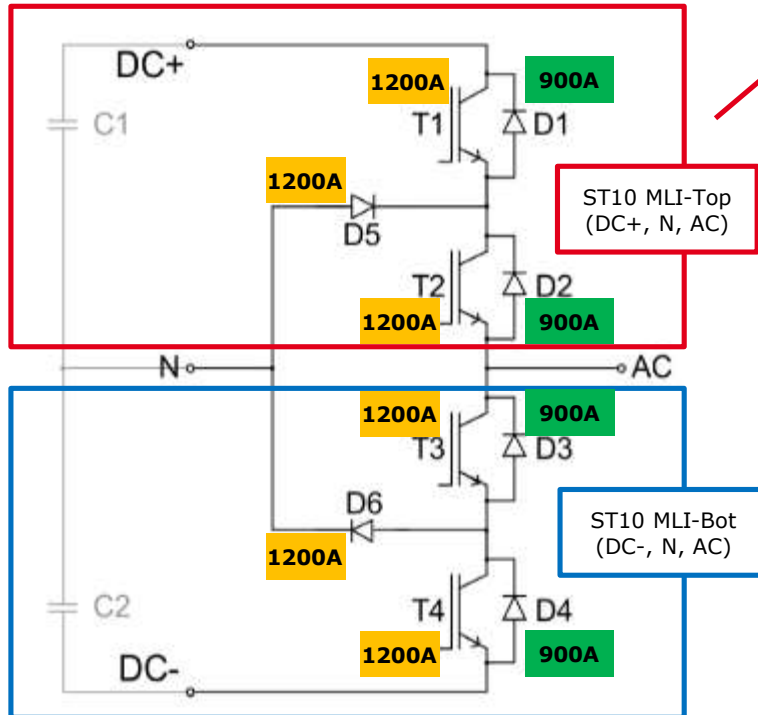


Not designed
for ESS

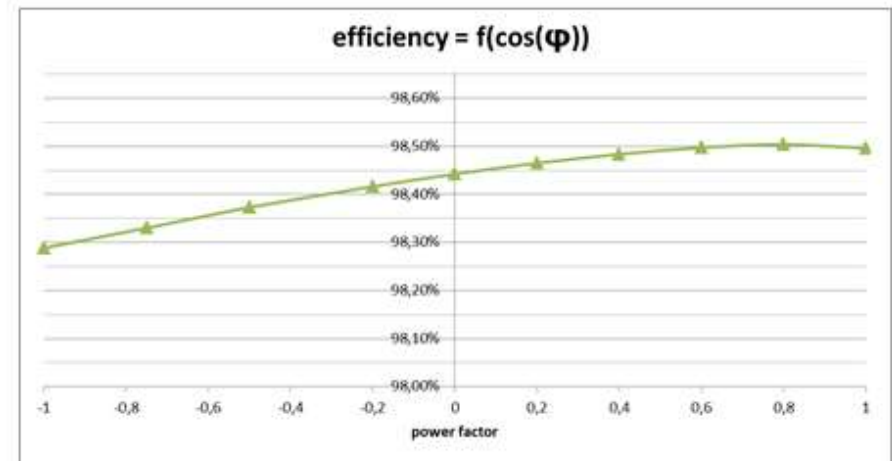
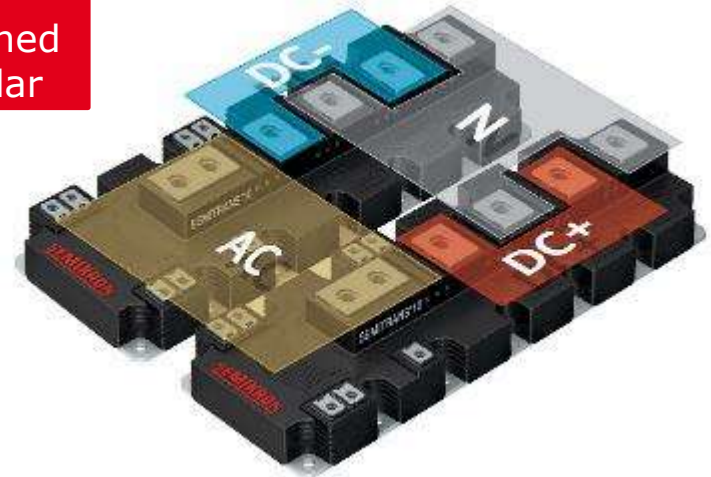
Fig. 4. S7 and L7 are implemented in the subsystems T1 to T4 and T5 to T6, respectively. Whereas T2 and T3 provide an I_{nom} of 200 A, all other IGBTs have an I_{nom} value of 400 A. With respect to the diode, two main scenarios are analyzed: in the first one, 200 A RAPID diodes are integrated in all subsystems. In the second

Source: Christian R. Müller, et al. "New 950-V IGBT and diode technology integrated in a low-inductive ANPC topology for solar applications", PCIM Euro, 2019

State of the art power modules for solar application - Central



Designed for solar



Packaging Technology in different Application



Introduction of solar & ESS

2-level & 3-level features

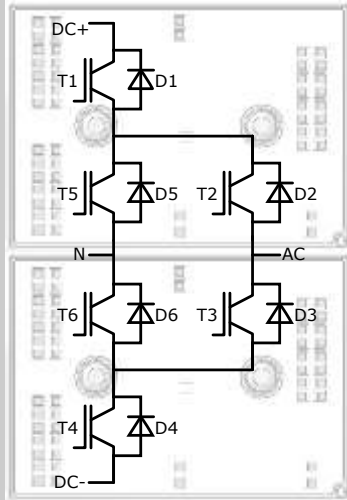
3-level for ESS & Solar (ANPC)

3-level Central Converter Design

3-level Commutation Difficulties

Summery

Split ANPC solution with optimized chips for Solar and ESS

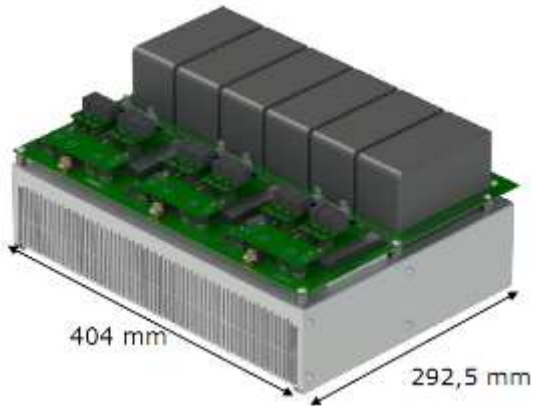


Chip configuration for Solar

Switch	Chip	Technology	I_{nom}	Voltage	Amount	I_{total}
T1/T4	IGC86T95U12RS	S7	200A	950V	3	600A
T5/T6	IGC86T95U12RS	S7	200A	950V	1	200A
D1/D4	IDC29D95Q8	EC7	100A	950V	3	300A
D5/D6	IDC29D95Q8	EC7	100A	950V	3	300A
T2/T3	IGC86T95U12RV	L7	200A	950V	2	400A
D2/D3	SKCD53C120I4F	CAL4F	100A	1200V	3	300A

Chip configuration for ESS

Switch	Chip	Technology	I_{nom}	Voltage	Amount	I_{total}
T1/T4	IGC86T95U12RS	S7	200A	950V	3	600A
T5/T6	IGC86T95U12RS	S7	200A	950V	3	600A
D1/D4	IDC29D95Q8	EC7	100A	950V	6	600A
D5/D6	IDC29D95Q8	EC7	100A	950V	4	400A
T2/T3	IGC86T95U12RV	L7	200A	950V	2	400A
D2/D3	SKCD53C120I4F	CAL4F	100A	1200V	5	500A



Split ANPC for Solar

Operation condition:

$V_{dc} = 1350V$

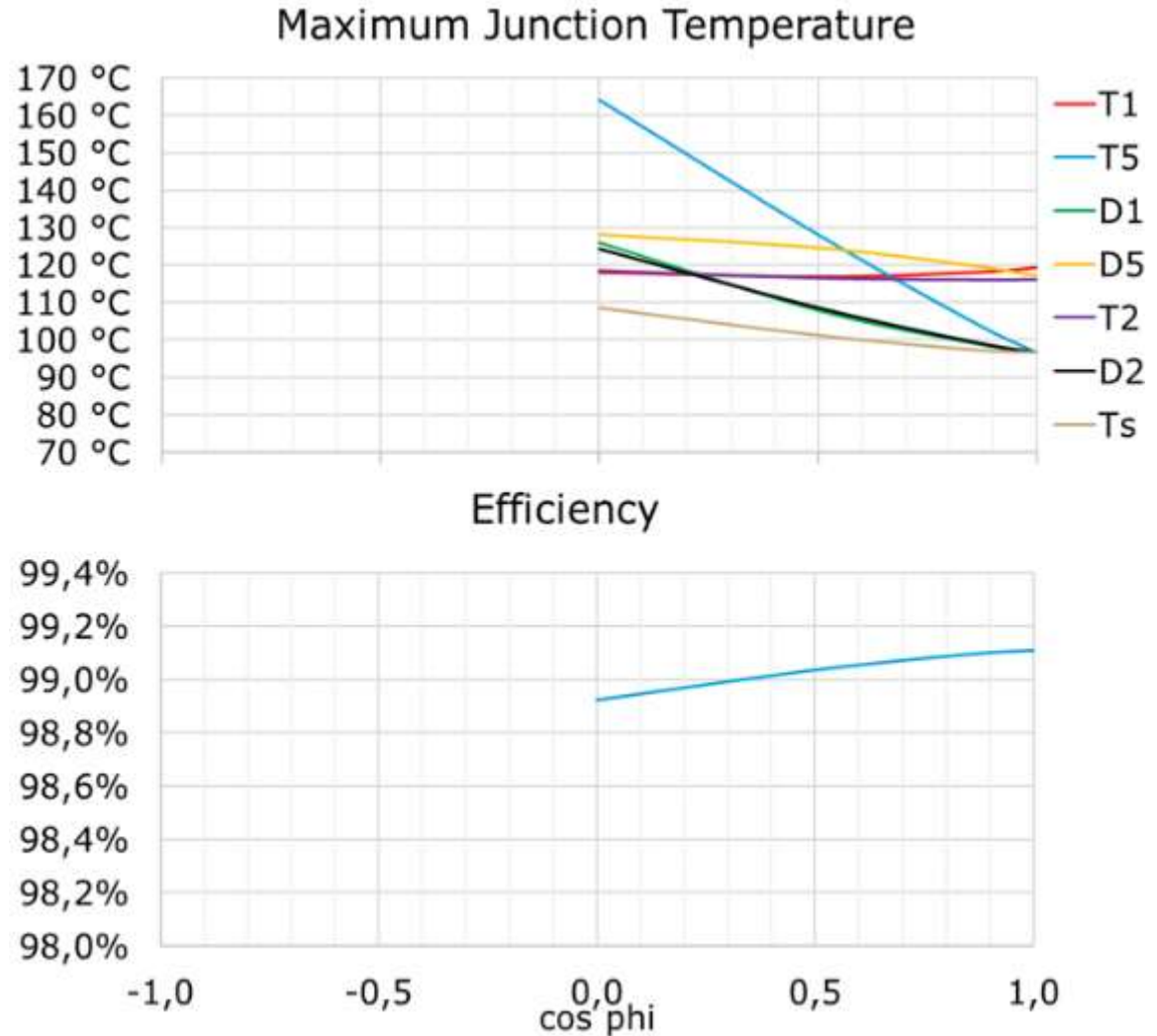
$V_{out} = 800V$

$P_{out} = 277kW$

$f_{sw} = 16kHz$

$T_a = 40^{\circ}C$

Cooling: air



Split ANPC for ESS

Operation condition:

$V_{dc} = 1400V$

$V_{out} = 690V$

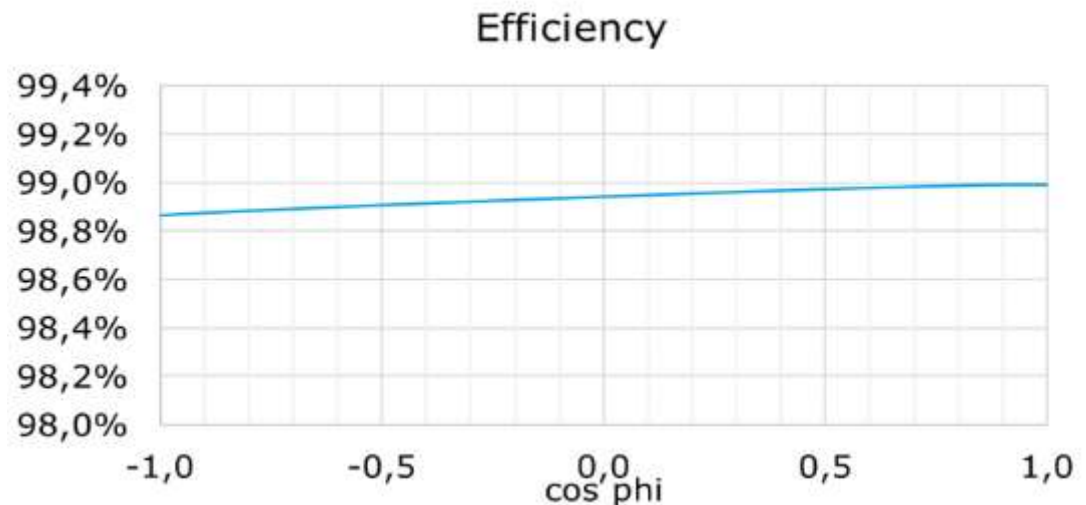
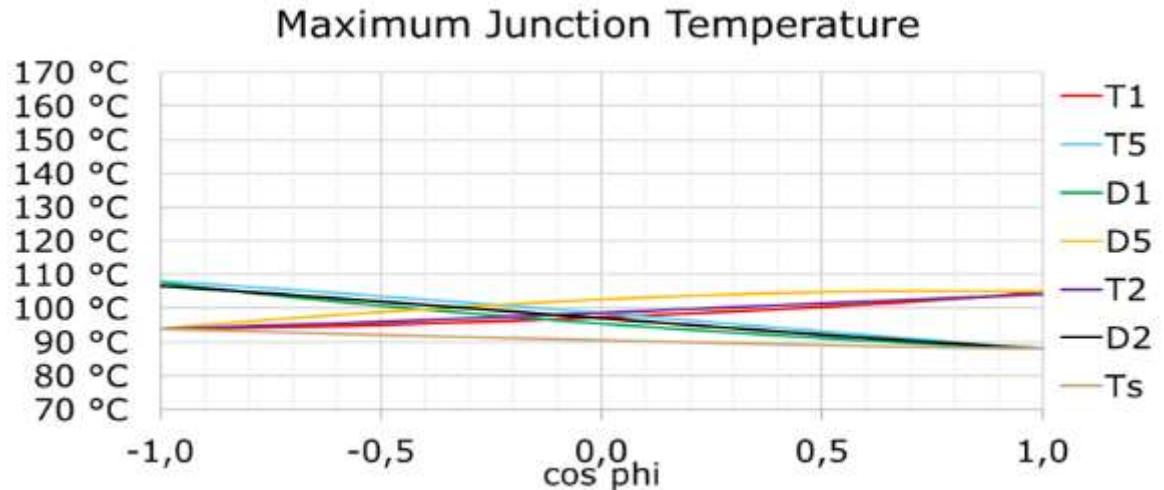
$P_{out} = 225kW$

$f_{sw} = 16kHz$

$T_a = 40^{\circ}C$

Cooling: air

Output power should reach to 300kW



SKiiP 38ANPC10S7V10

3 level ANPC split (TOP)

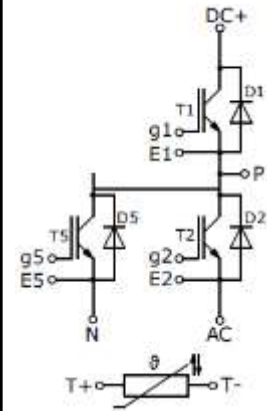
Target Data

Features

- 7th generation IGBTs in 950V
- Highly reliable spring contacts for electrical connections
- NTC T-Sensor

Typical Applications

- Energy storage



MiniSKiiP® 3

Si-Version	T1/T4/T5/T6	D1/D4	D5/D6	T2/T3	D2/D3
I_{nom} [A]	600	600	400	400	500
Performance	S7	EC7	EC7	L7	CAL4F
V_{ce}/V_f @150°C	2.2 V	2.15 V	2.15 V	1.35 V	2.15 V
E_{on}^* [mJ]	30.5	-	-	Not considered	Not considered
E_{off}^* [mJ]	24.4	13.2	8.8	Not considered	Not considered

* at $T_j=150^\circ\text{C}$, $I=I_{nom}$, $V_c=600\text{V}$

SKiiP 38ANPC10S7V20

3 level ANPC split (BOT)

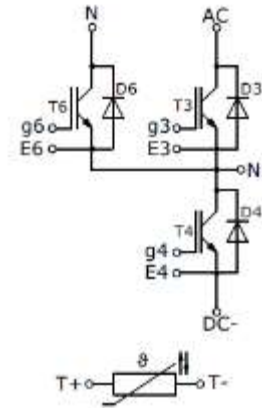
Target Data

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MiniSKiiP® 3

Si-Version	T1/T4/T5/T6	D1/D4	D5/D6	T2/T3	D2/D3
I_{nom} [A]	600	600	400	400	500
Performance	S7	EC7	EC7	L7	CAL4F
V_{ce}/V_f @150°C	2.2 V	2.15 V	2.15 V	1.35 V	2.15 V
E_{on}^* [mJ]	30.5	-	-	Not considered	Not considered
E_{off}^* [mJ]	24.4	13.2	8.8	Not considered	Not considered

* at $T_j=150^\circ\text{C}$, $I=I_{nom}$, $V_c=600\text{V}$

Packaging Technology in different Application



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Summery

Focus Solar Central Inverter

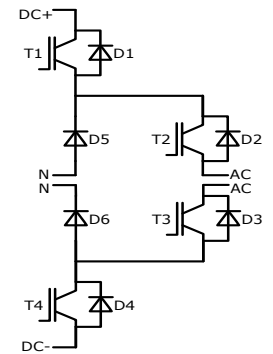
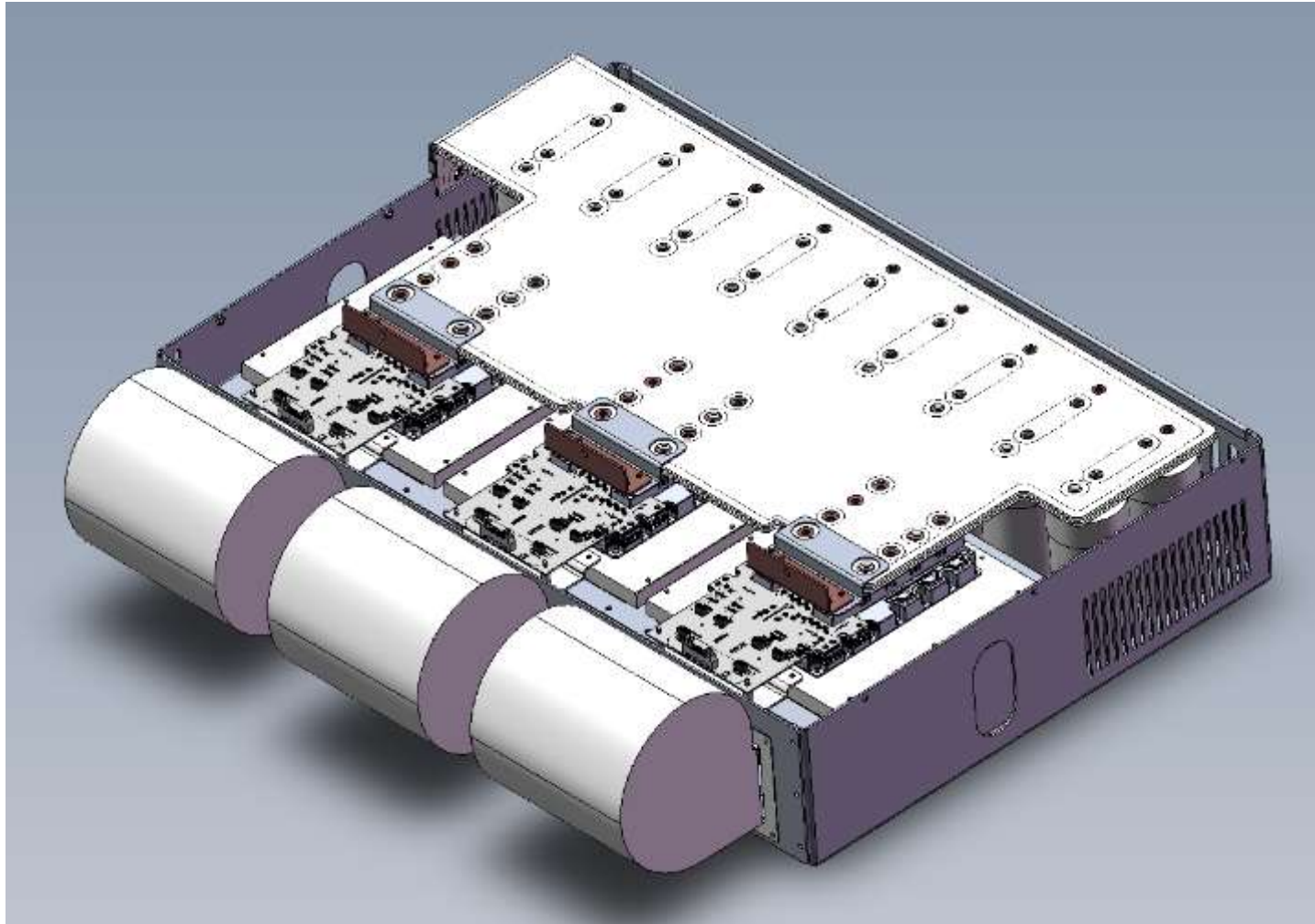


Which power module is matching with your requirements?

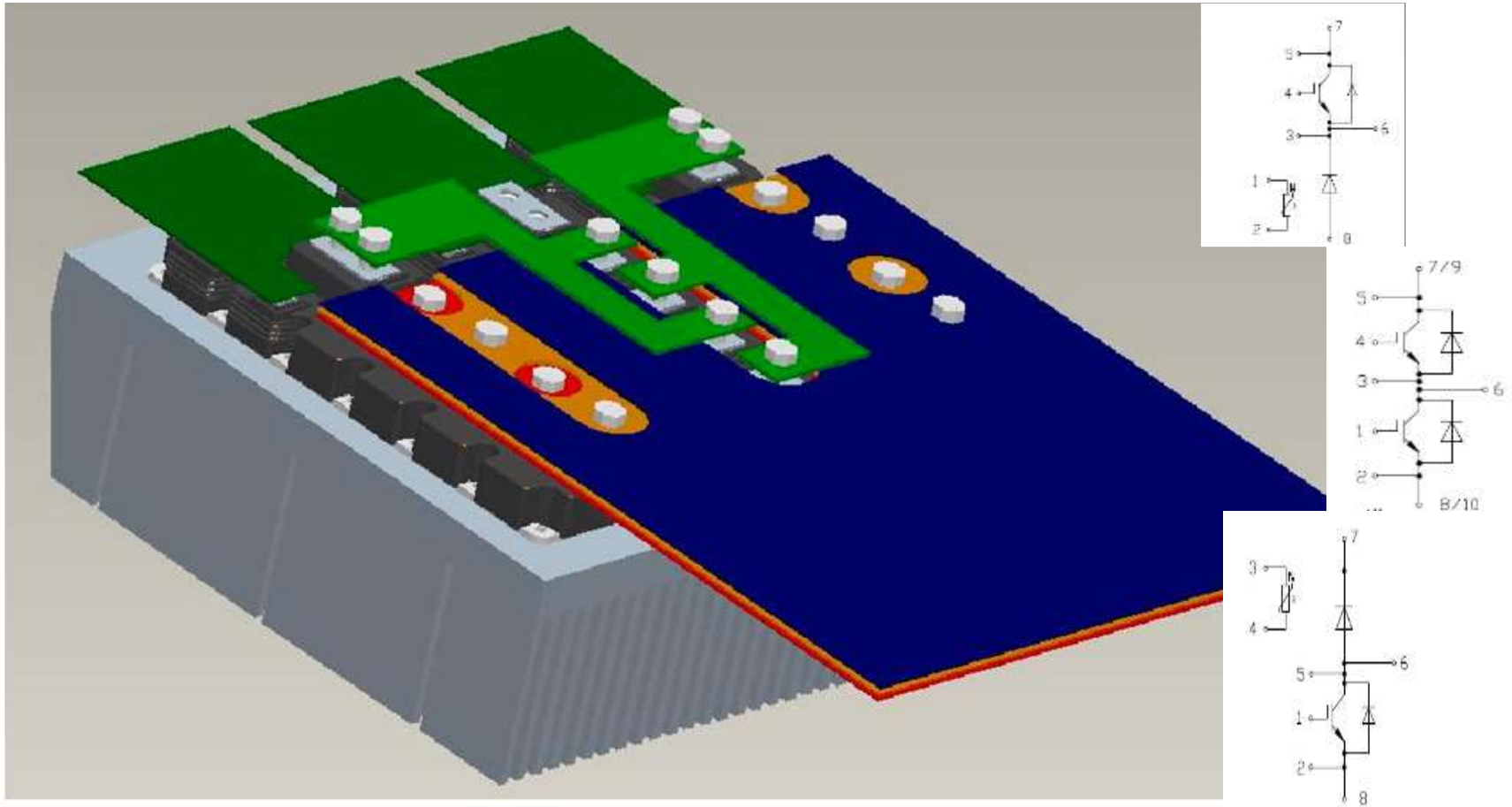
- cost of power module
- system cost
- current density



3 Phase Solar Inverter Design 500-750kW

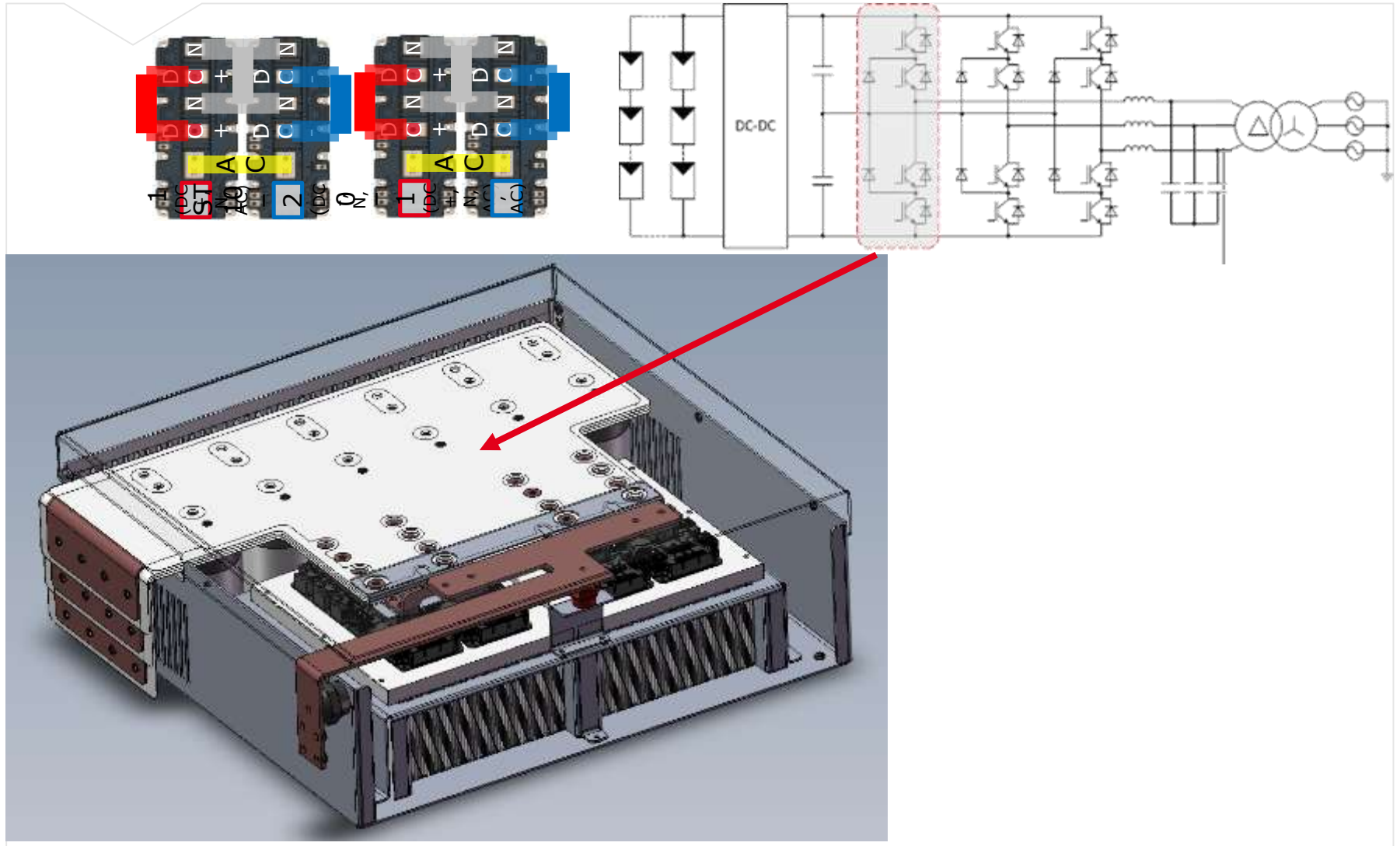


3-level-design with Primepack – Infineon Application proposal



3 level topology with PrimePACK™ halfbridge and chopper FD and DF

1 - 1.5MW Solar Converter – one phase (2 pairs in parallel)

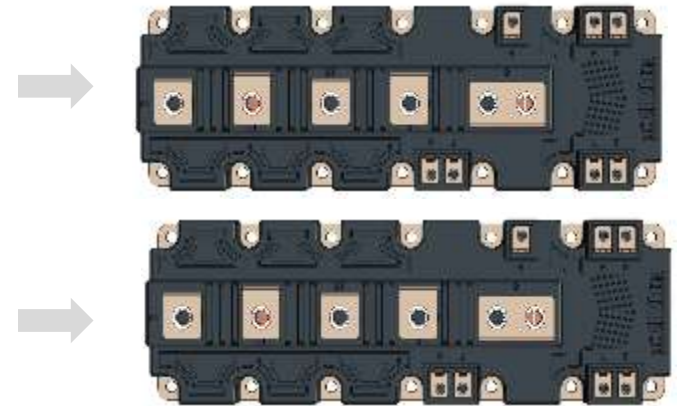


Goal:

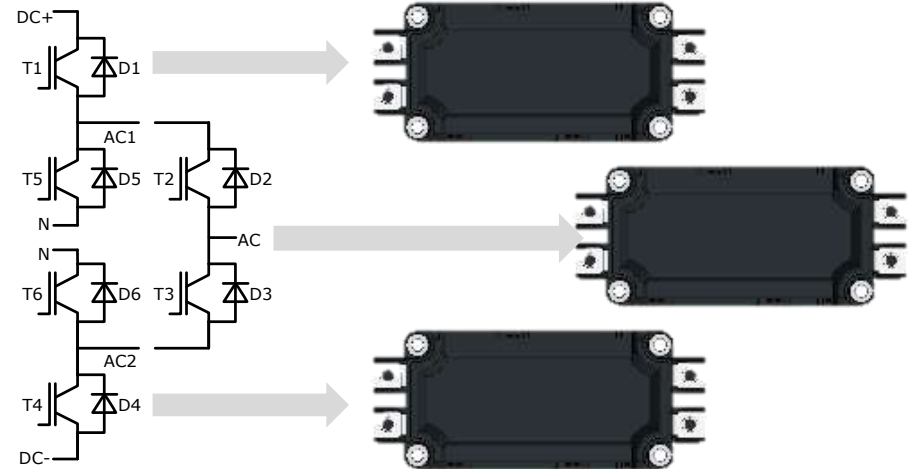
Comparison among
Semitrans 10 split NPC vs.
SEMiX3p based NPC with
respect to:

- Material
- Manufacturing
- Performance

SEMITRANS
split NPC



SEMiX3p

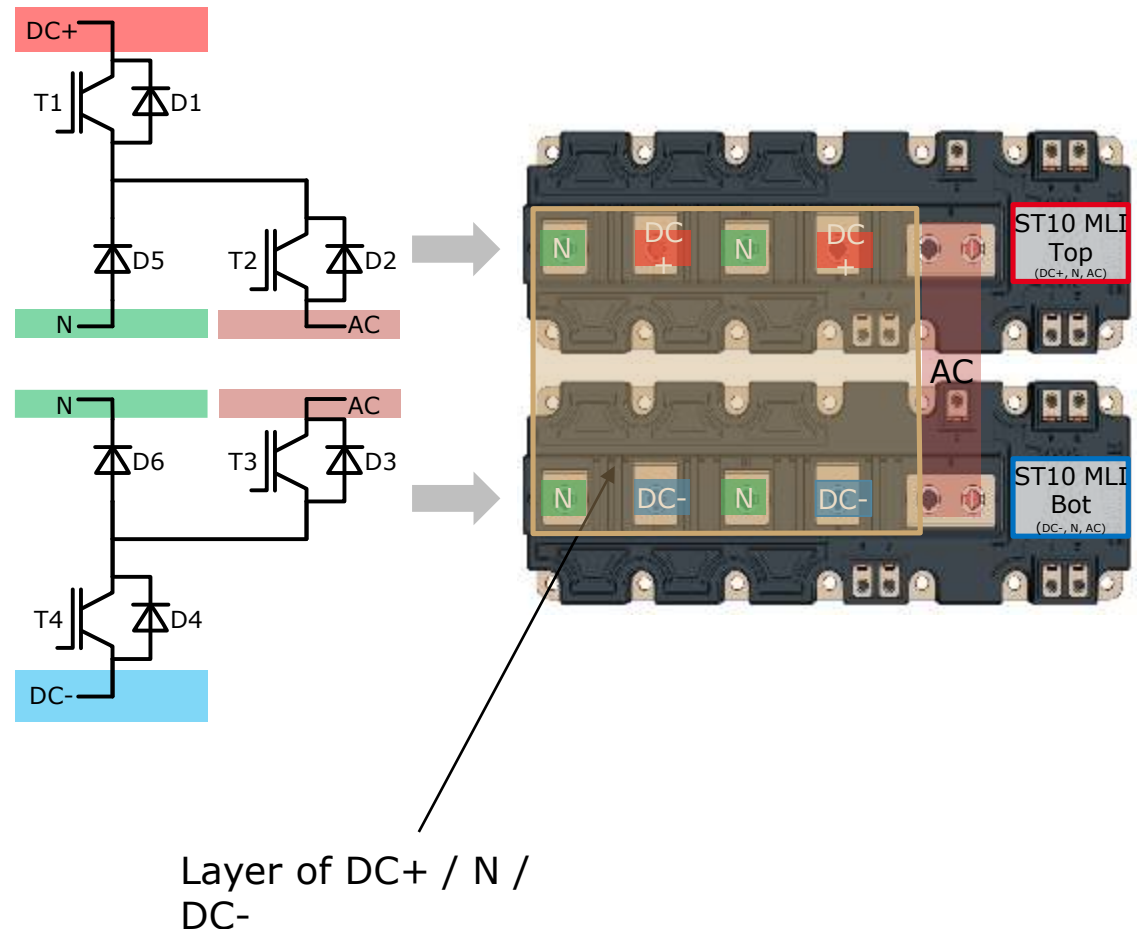


ST10 split NPC

DC+ / N / DC-
overlapping → **reduced
DC Link inductance**

Partly overlapping with AC
terminal to **further
reduce stray inductance
down to 64nH** between
two modules

The colors of the terminals relate to
the colors of the drawing



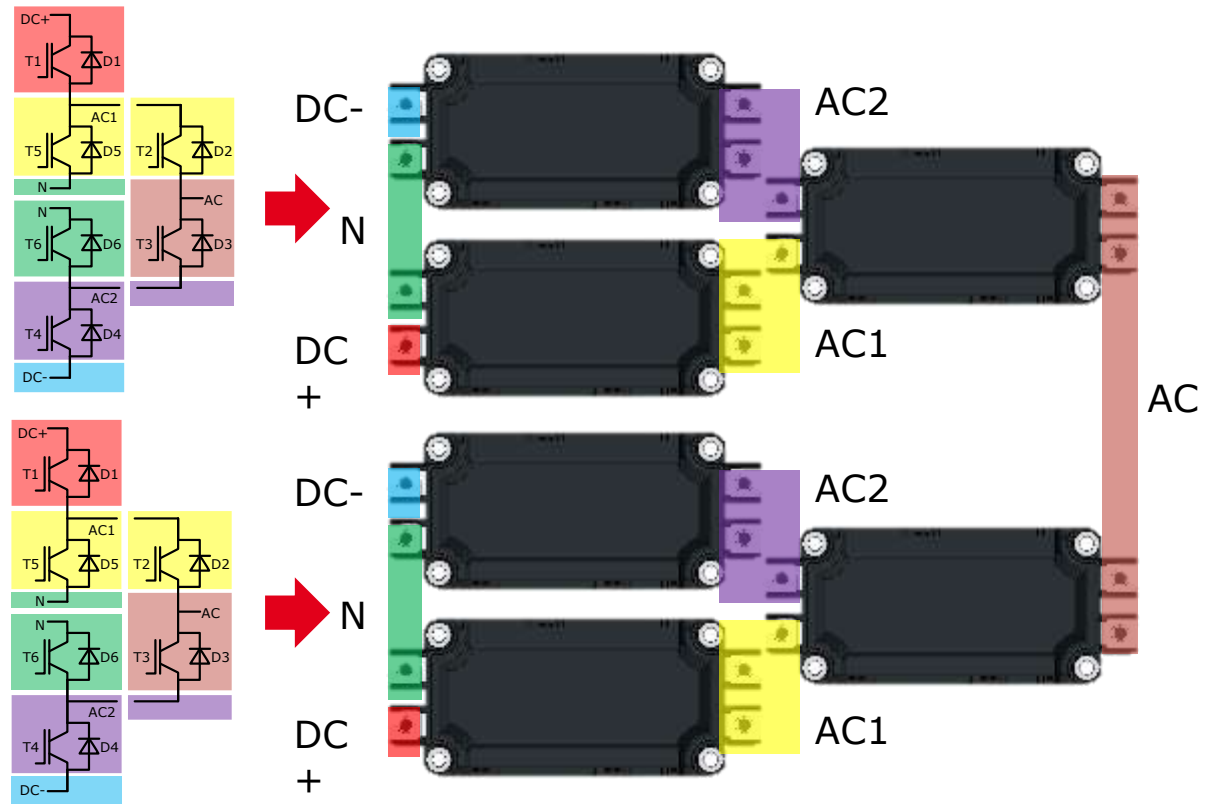
SEMiX3p as NPC

No overlapping of all 5 DC layers possible →
increased DC Link inductance

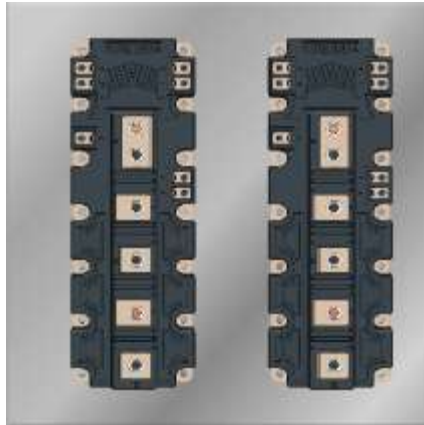
Probably **AC-choke** necessary for current balance

No Common driver board possible

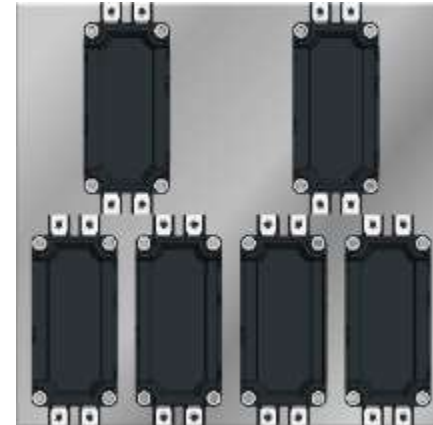
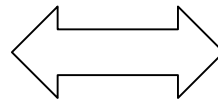
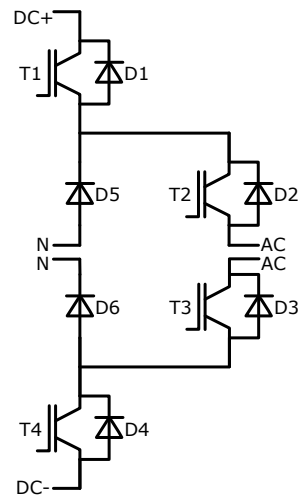
The colors of the terminals relate to the colors of the drawing



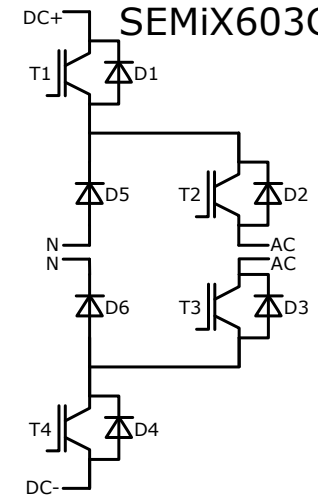
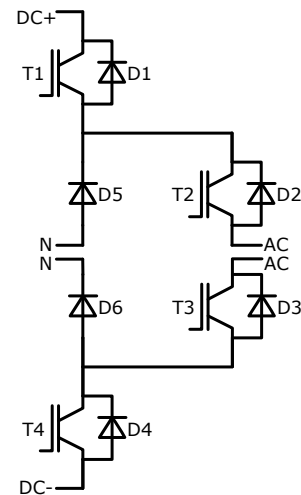
Equivalent setup



SKM1200MLI12E4
SKM1400MLI12M7



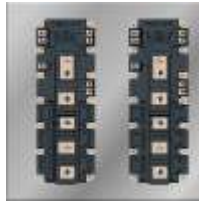
SEMiX603GB12E4



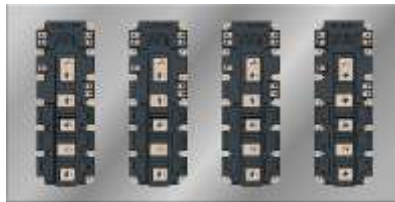
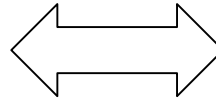
Scalability

SKM1200MLI12E4
SKM1400MLI12M7

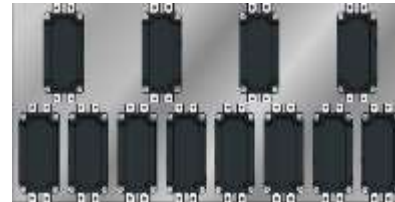
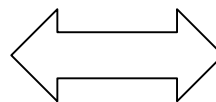
SEMiX603GB12E4



equivalent



equivalent



Heat sink

Assumption:

Both module variants use the same heat sink

Standard heat sink from Mersen

Serrated fin with Alpha fin option

TOP View

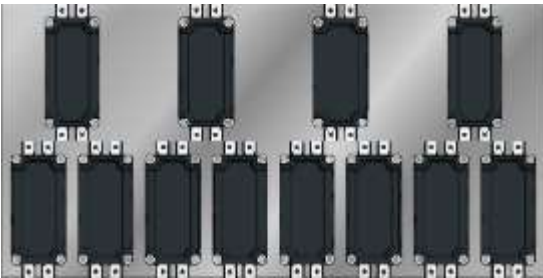


Front View



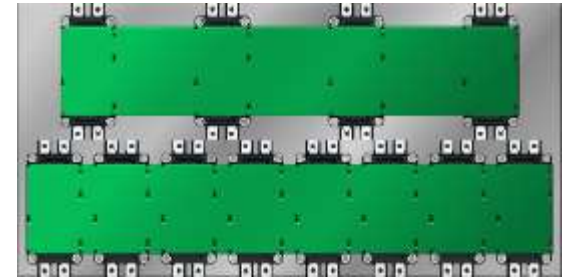
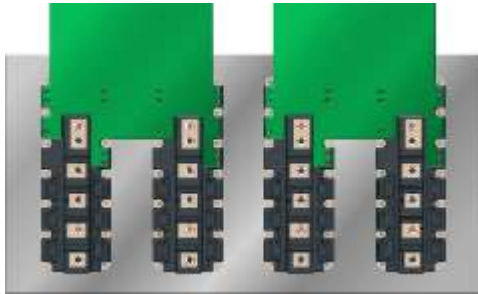
Heat sink	Value
Length [mm]	600.00
Width [mm]	300.00
Fin pitch [mm]	5.49
Fin thickness [mm]	1.25
Fin length [mm]	89.00
Root thickness [mm]	12.7
Weight [kg]	13.9

Screws – Module to heat sink



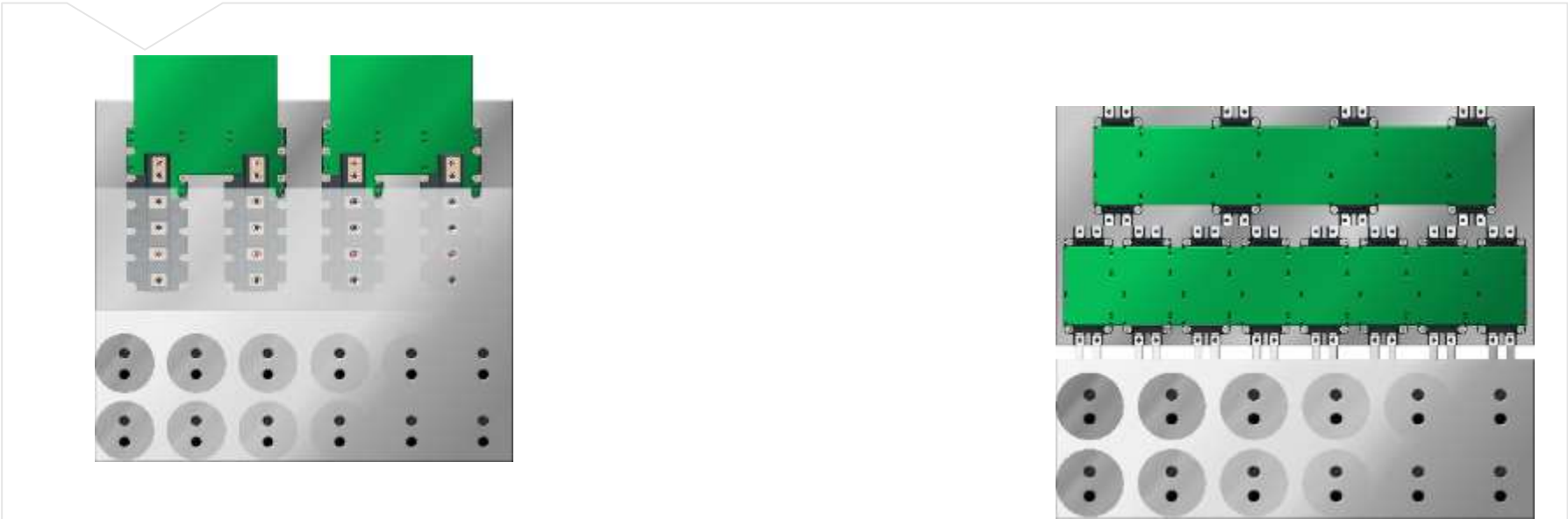
Semitrans10 split NPC		Screws		SEMiX3p	
Amount	cost			Amount	cost
56x M5		Module to heat sink		48x M5	

Screws – Driver



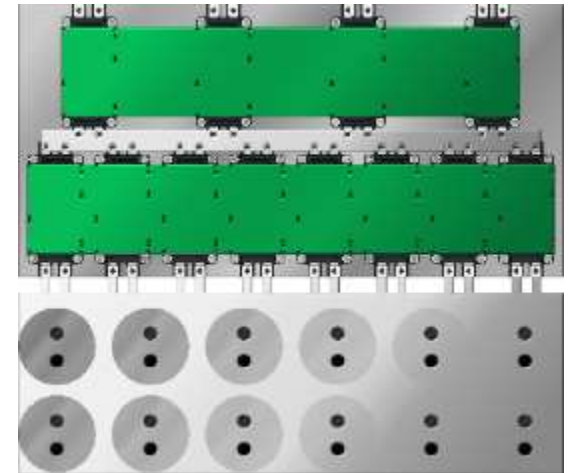
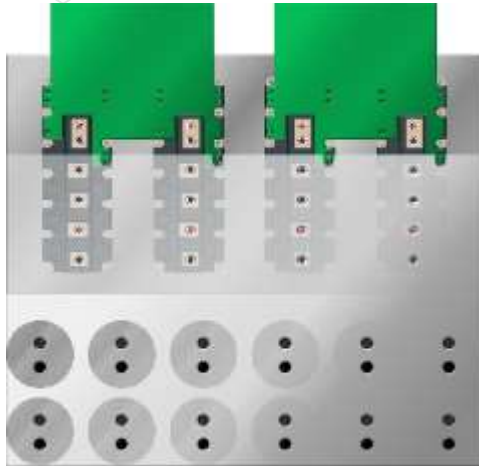
Semitrans10 split NPC		Screws		SEMiX3p	
Amount	cost			Amount	cost
56x M5		Module to heat sink		48x M5	
28x M4		Driver		48x M2.5	

Screws – DC Link to module



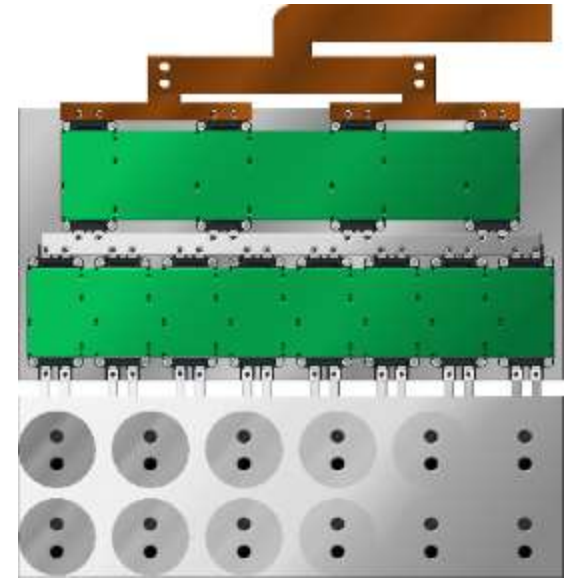
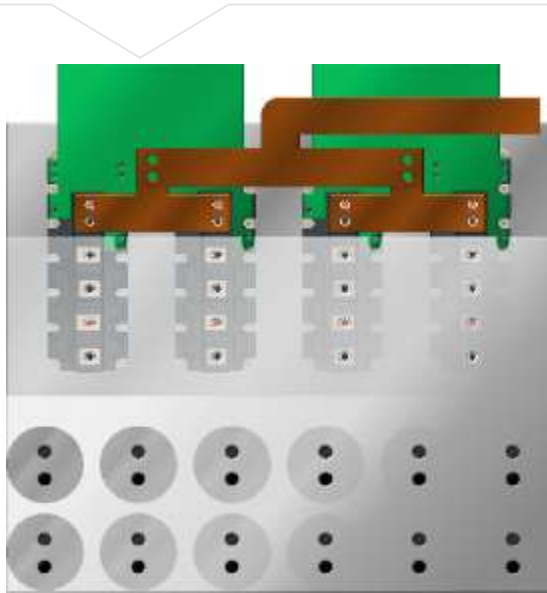
Semitrans10 split NPC		Screws	SEMiX3p	
Amount	cost		Amount	cost
56x M5		Module to heat sink	48x M5	
28x M4		Driver	48x M2.5	
16x M8		DC Link to module	16x M6	

Screws – Output stage



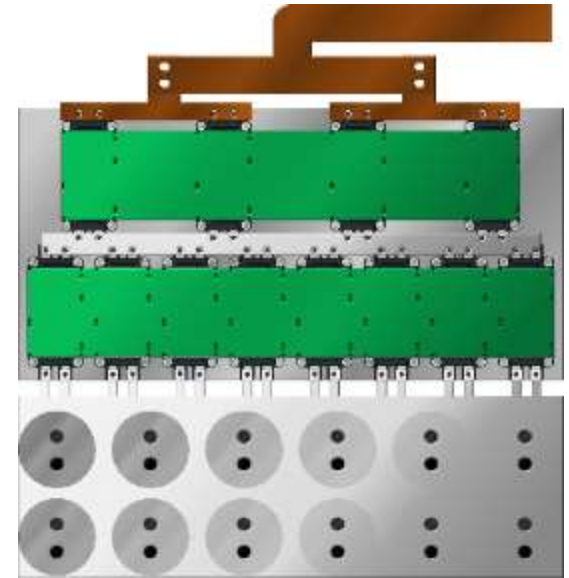
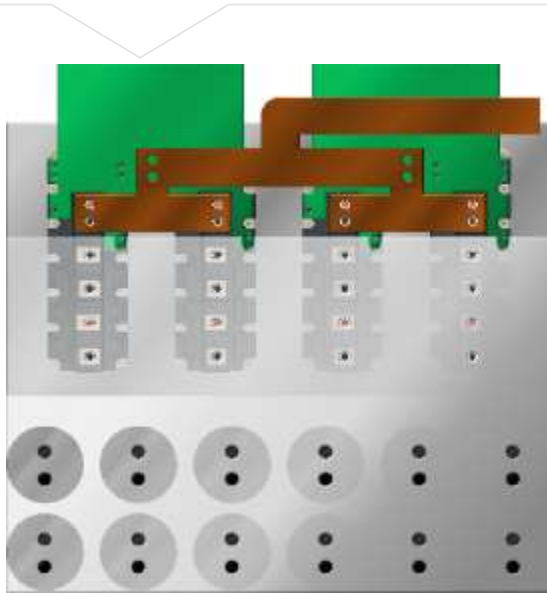
Semitrans10 split NPC		Screws	SEMiX3p	
Amount	cost		Amount	cost
56x M5		Module to heat sink	48x M5	
28x M4		Driver	48x M2.5	
16x M8		DC Link to module	16x M6	
-		Output stage	24x M6	

Screws – AC bar to module



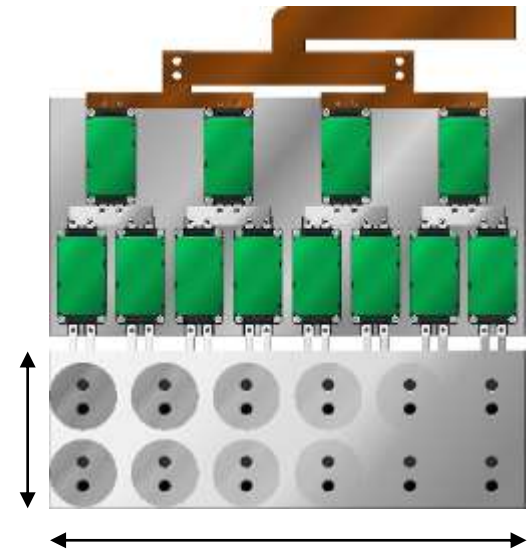
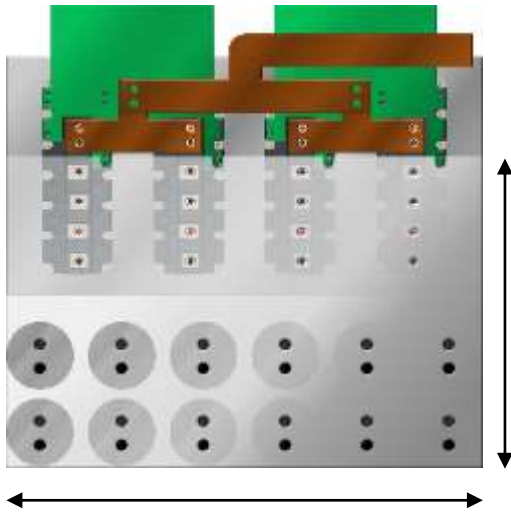
Semitrans10 split NPC		Screws	SEMiX3p	
Amount	cost		Amount	cost
56x M5		Module to heat sink	48x M5	
28x M4		Driver	48x M2.5	
16x M8		DC Link to module	16x M6	
-		Output stage	24x M6	
8x M8		AC bar to module	8x M6	

Screws - Summary



Semitrans10 split NPC		Screws	SEMiX3p	
Amount	cost		Amount	cost
56x M5		Module to heat sink	48x M5	
28x M4		Driver	48x M2.5	
16x M8		DC Link to module	16x M6	
-		Output stage	24x M6	
8x M8		AC bar to module	8x M6	
106		Total screws	144	

DC Link



Semitrans10 split NPC

SEMiX3p

DC+ / N / DC-

DC Link Layers

DC+ / N / DC-

600

Width [mm]

600

392

Length [mm]

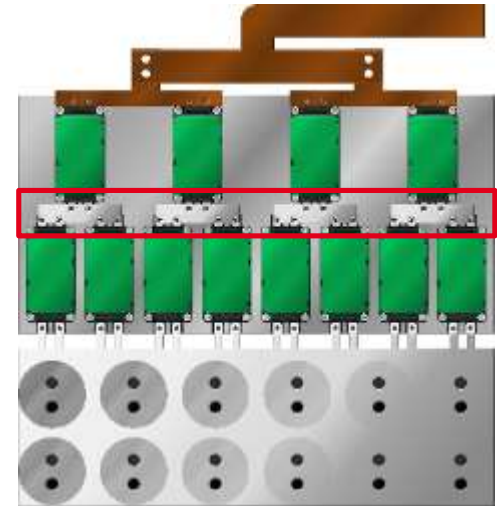
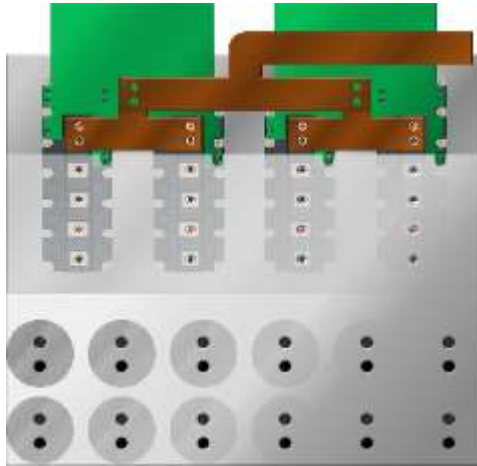
200

tbd

cost

tbd

output stage



Semitrans10 split NPC

SEMiX3p

-

Output stage Layers

Out 1 / Out 2

0

cost

tbd

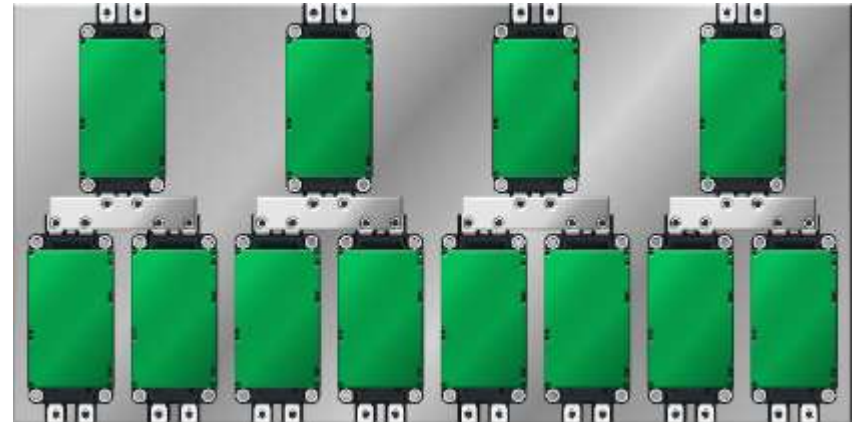
Driver

Driver board solution for SEMiX3p could be single drivers with adapters in between connected by control cable

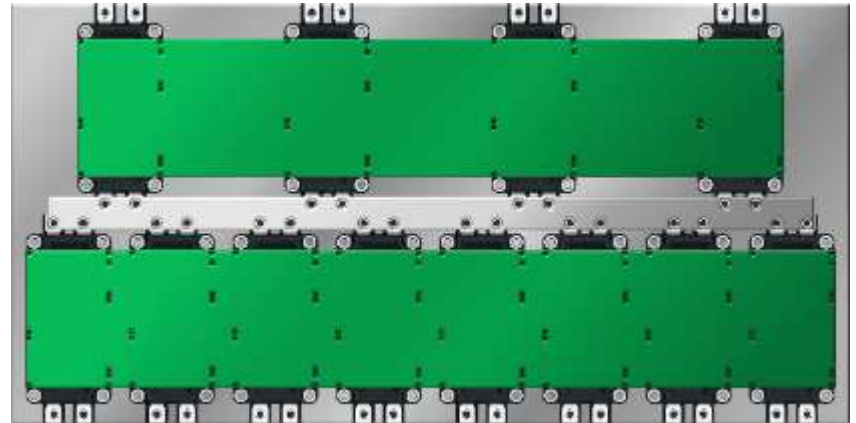
Up to

2 different driver PCB for input and output stage

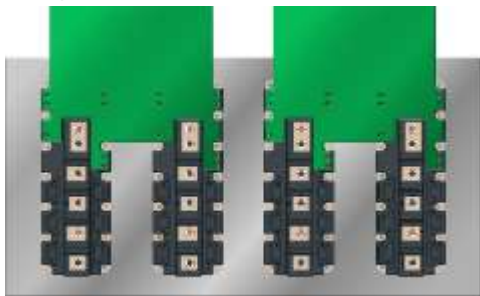
Single drivers



2 different driver boards



Driver PCB



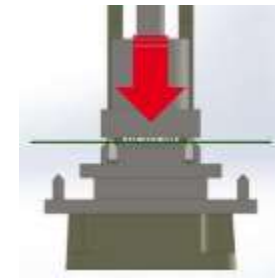
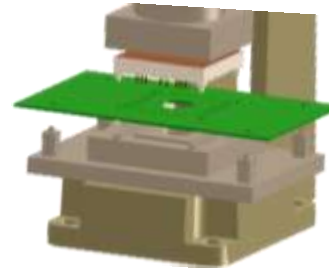
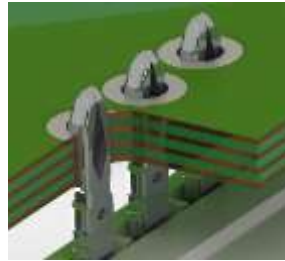
Semitrans10 split NPC	PCB	SEMiX3p
tbd	cost	tbd

Soldering / pressfit pins for SEMiX3p

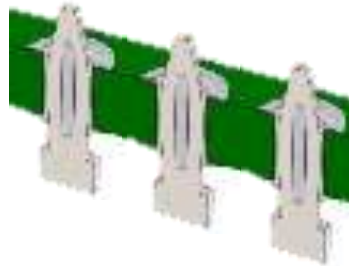
The pressfit SEMiX3p modules can either be connected to the PCB by pressfit or soldering.

In both cases different equipment is required with **additional costs**

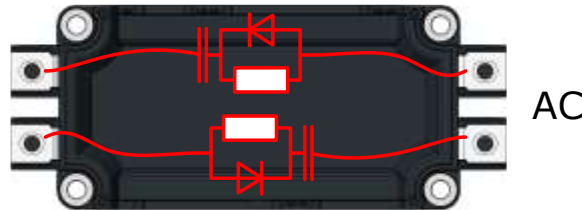
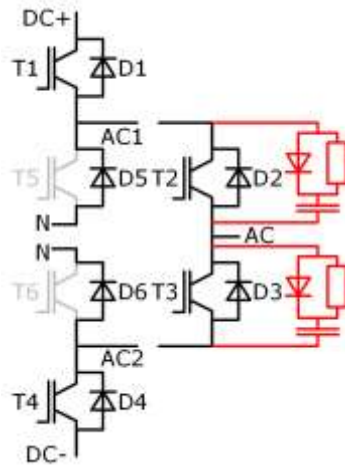
pressfit



pressfit



SEMiX3p – RCD snubber



Option	Mechanical construction	Remarks
1		Pressfit pins not connected
2		Probably insufficient contact between PCB and Output stage / AC bar connector
3		ok

SEMiX3p – RCD snubber

Operating area 1 and 3:
T2/T3 switching
→ RCD snubber active

Operating area 1 and 3:
T2/T3 no switching
→ RCD snubber not active

Power losses in RCD
snubber depend on
application condition

In solar application RCD
snubber less active than in
wind application

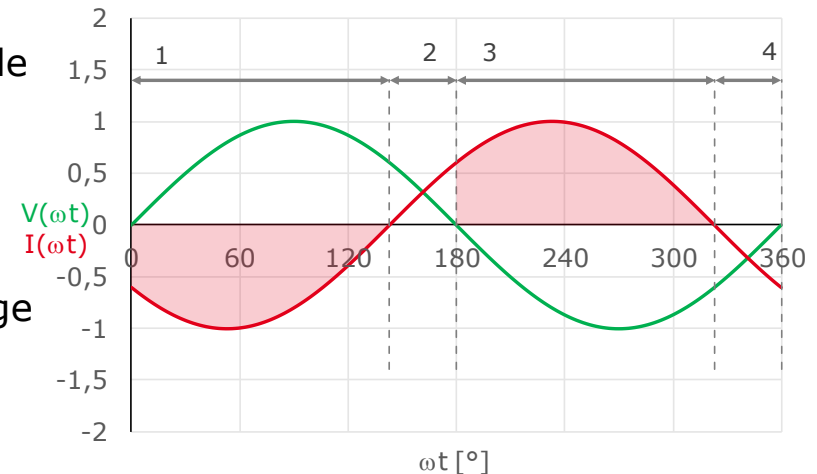
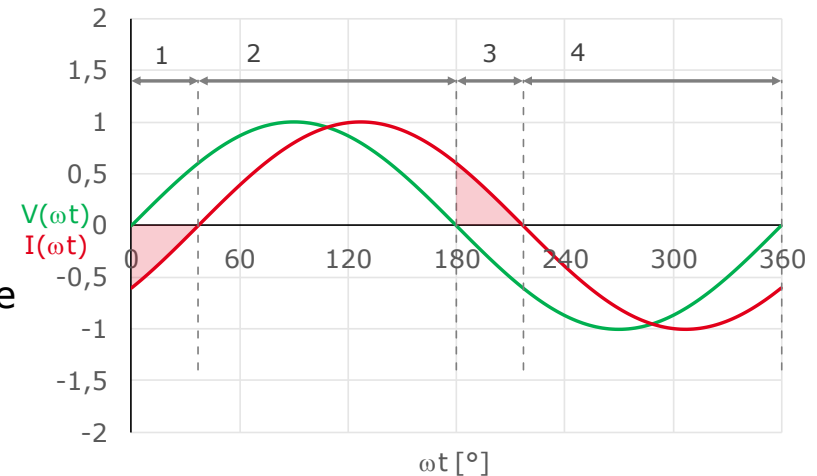
→ **Additional losses in
snubber for SEMiX3p
solution**

Solar:
 $\cos\phi=0.8$
→ RCD snubber
active for 40°

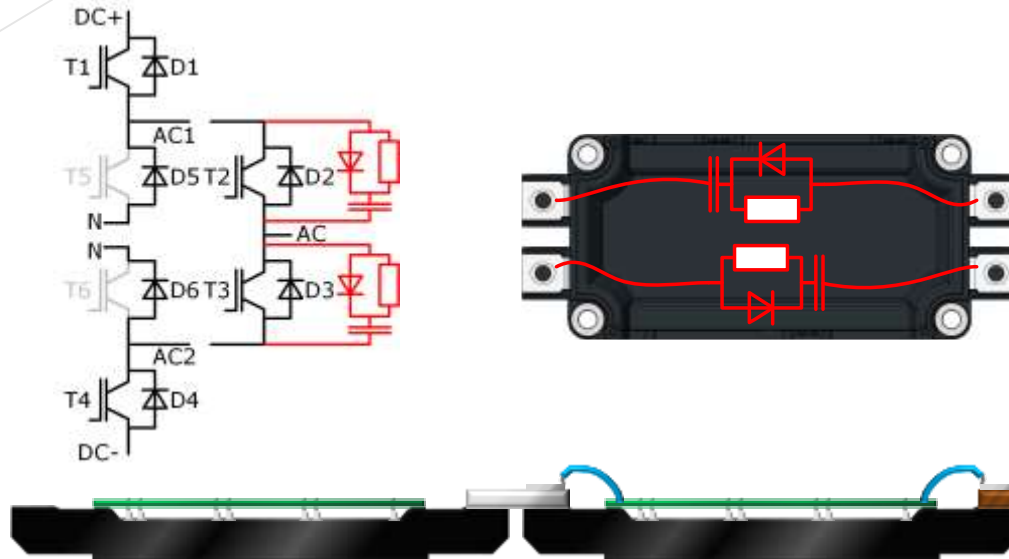
60% of $I_{\max}$
→ lower overvoltage

Wind: generator side
 $\cos\phi=-0.8$
→ RCD snubber
active for 140°

100% of $I_{\max}$
→ higher overvoltage



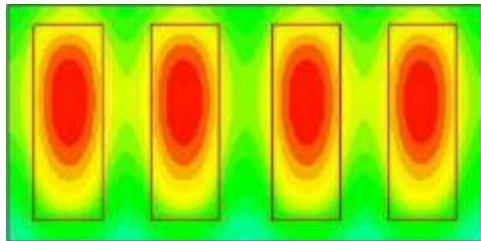
SEMiX3p – Summary RCD snubber



RCD snubber		Cost	Per module	Total costs
Diode			2	tbd
Resistor			2	tbd
Capacitor			2	tbd
heat sink for diode			2	tbd
Cable			4	tbd
				tbd

Solar application

4x SEMITRANS10 split NPC



1000m³/h

Solar application:

$V_{DC} = 1200 \text{ V}$

$V_{LL} = 550 \text{ V}$

$I_{out} = 1365 \text{ A}$

$P_{out} = 1.3 \text{ MW}$

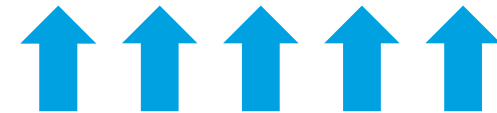
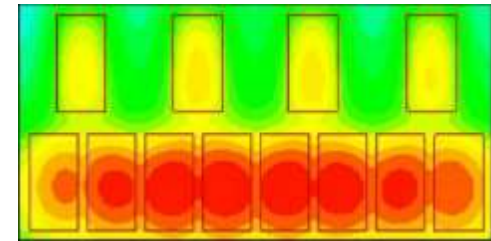
$f_{out} = 50 \text{ Hz}$

$f_{sw} = 4 \text{ kHz}$

$\cos\phi=1$

Cooling: air

12x SEMiX3p



1000m³/h

Semitrans10 split NPC		SEMiX3p
SKM1400MLI12M7		SEMiX603GB12E4
1000	Air volume [m³/h]	1000
0,0118 (100%)	R_{thj-s} [K/W] for all modules	0,0108 (92%)
120	T_{jmax} [°C]	122
4807 (100%)	Total Power losses Inverter [W]	5332 (111%)
-	Power losses RCD snubber [W]	tdb
4807 (100%)	Total Power losses [W]	5332 + tdb

Summary costs

SEMITRANS10 split NPC			Material costs			SEMiX3p		
tbd			Module costs			tbd		
tbd			Screw costs			tbd		
0			RCD network			tbd		
tbd			DC Link			tbd		
0			Output stage			tbd		
			Driver					
SEMITRANS10 split NPC			Labour costs			SEMiX3p		
tbd			Mounting			tbd		
0			Soldering / pressfit			tbd		

Packaging Technology in different Application



Introduction of solar & ESS

2-level & 3-level features

3-level for ESS & Solar (ANPC)

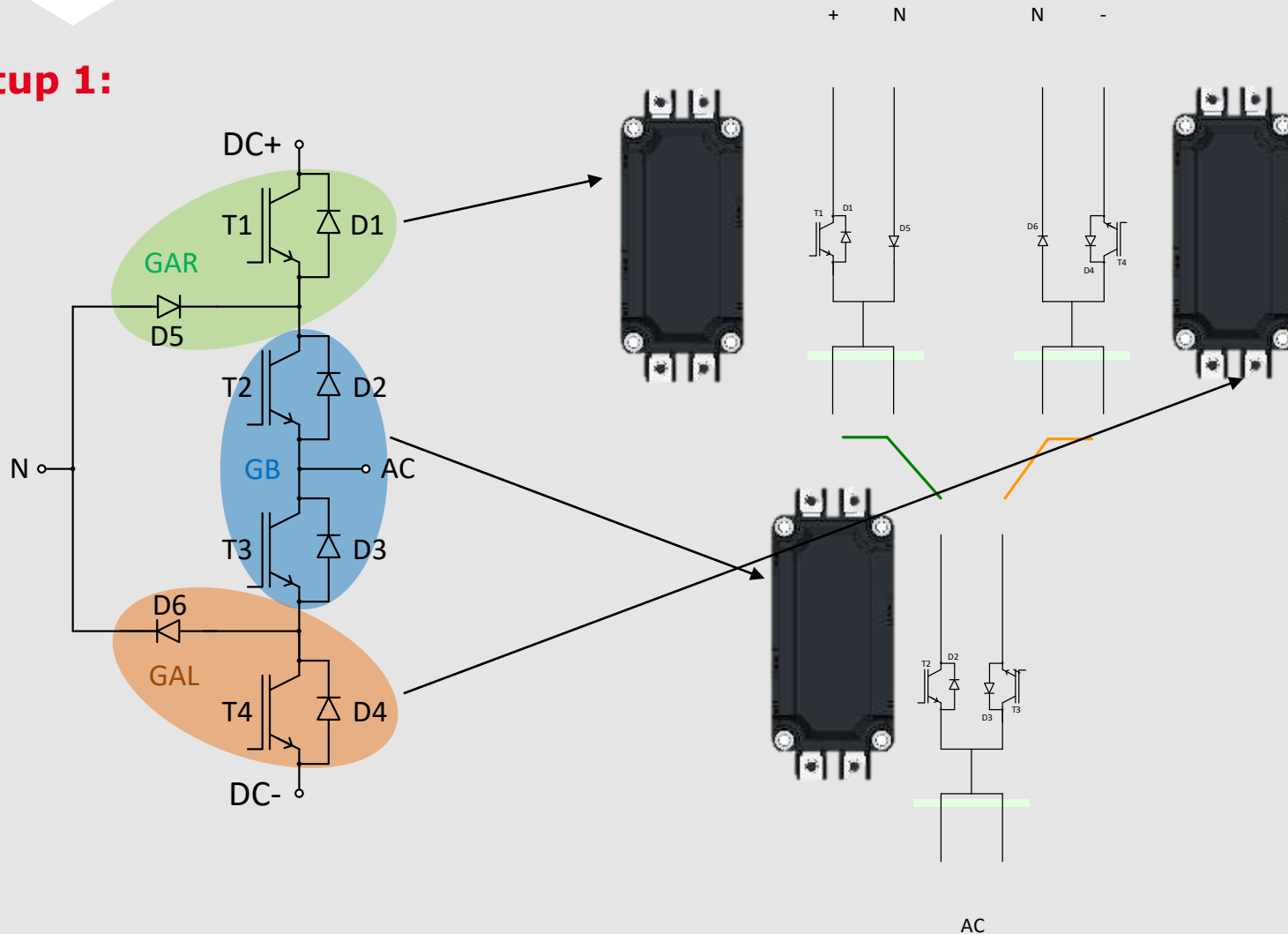
3-level Central Converter Design

3-level Commutation Difficulties

Summery

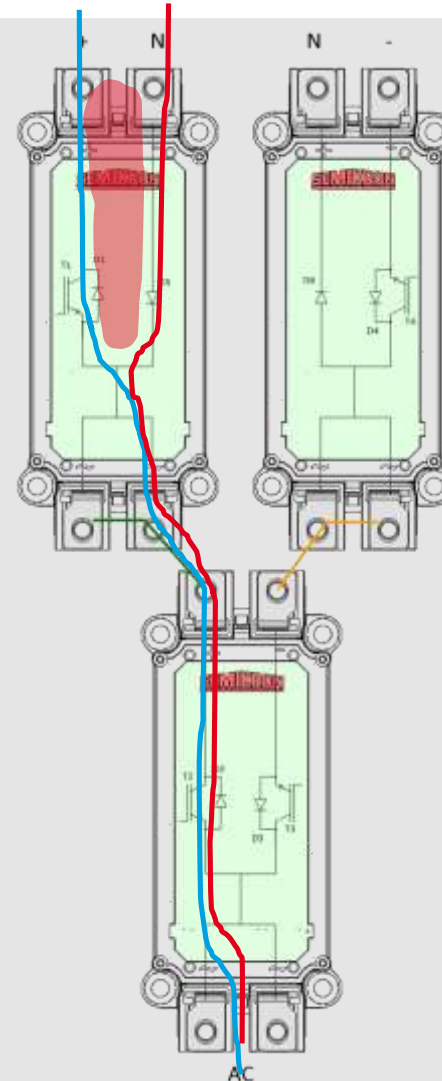
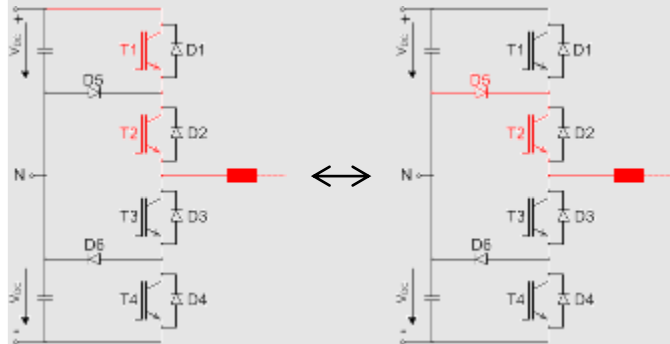
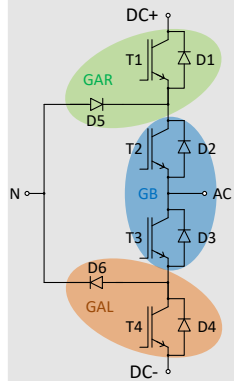
GAR(GB), GB and GAL(GB): Setup 1

Setup 1:



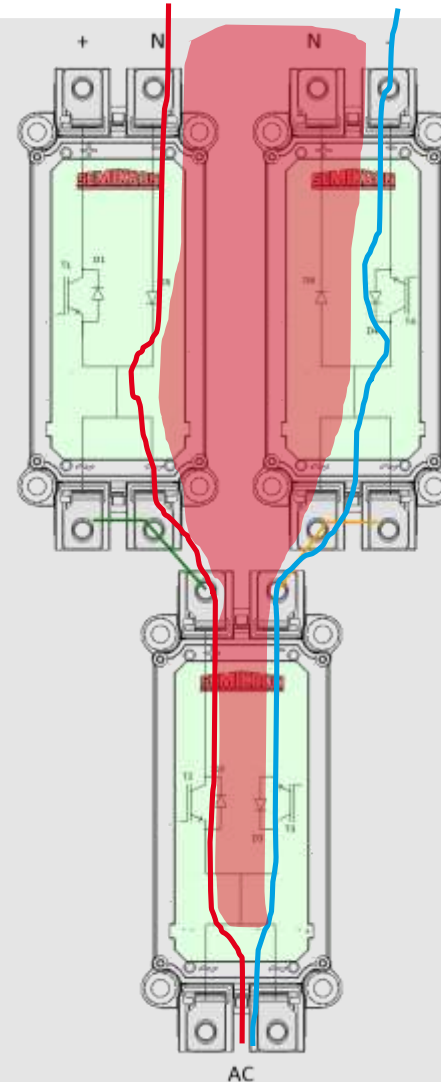
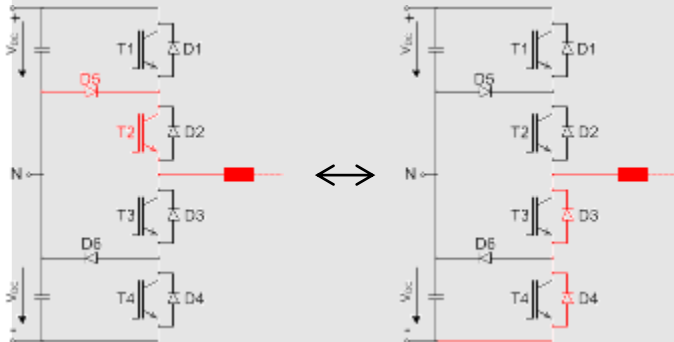
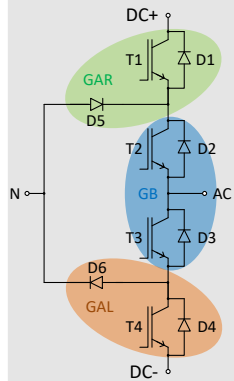
GAR, GB and GAL: Setup 1

Setup 1: current paths and short commutation loop T1/T2 $\Leftrightarrow$ D5/T2



GAR, GB and GAL: Setup 1

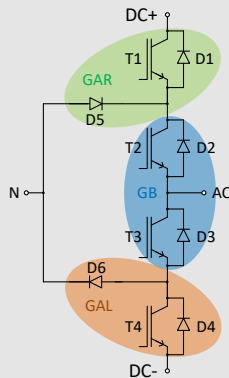
Setup 1: current paths and long commutation loop D5/T2 $\leftrightarrow$ D3/D4



GAR, GB and GAL: Setup 1

Setup 1 stray inductances:

- **Short commutation path inside one module: 35nH**
- **Long commutation path across module boundaries: 127nH**

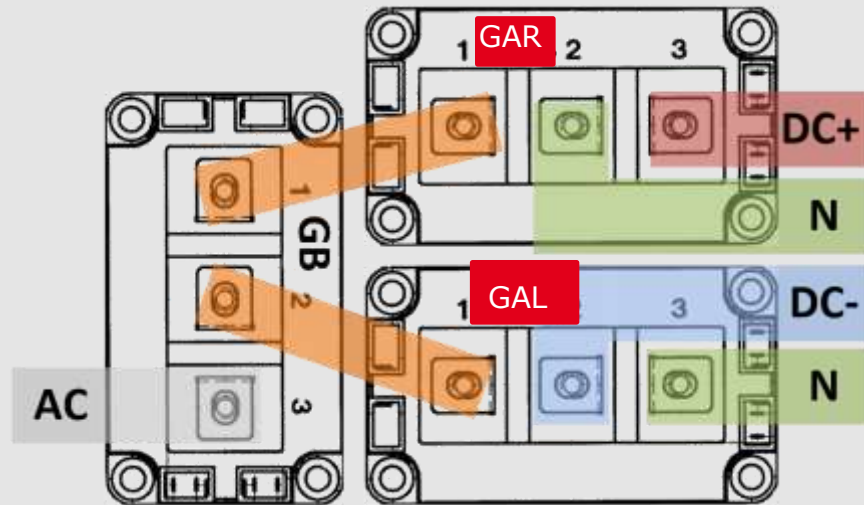
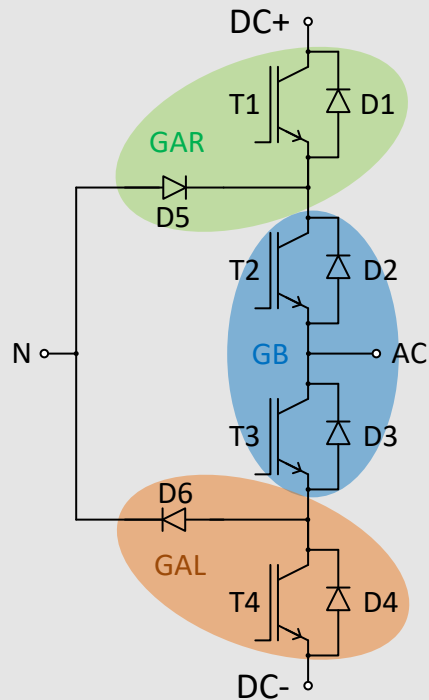


35nH

127nH

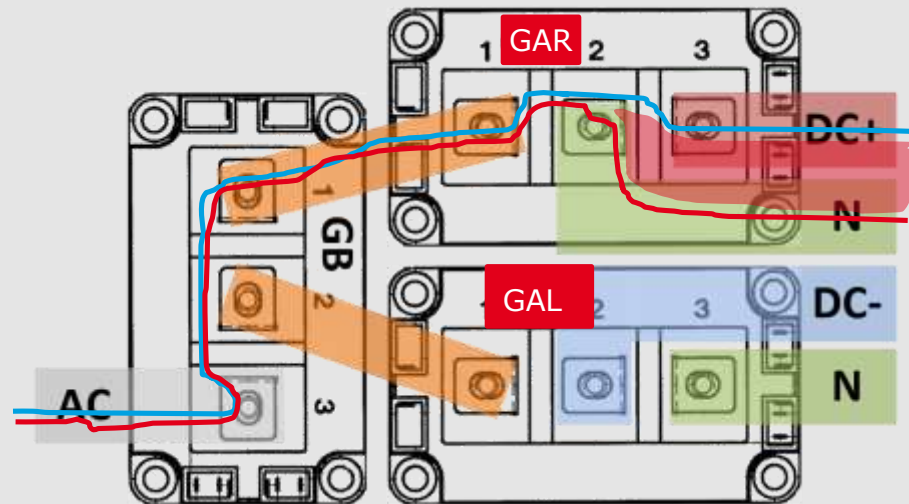
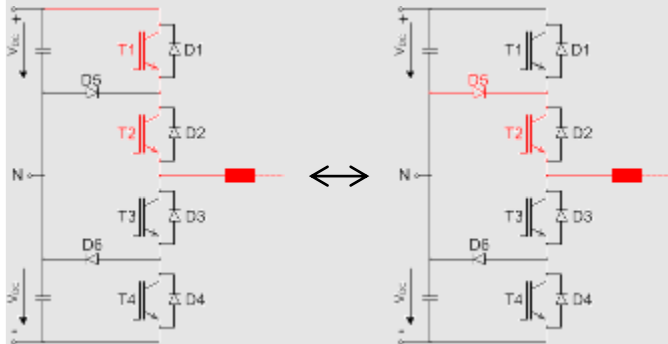
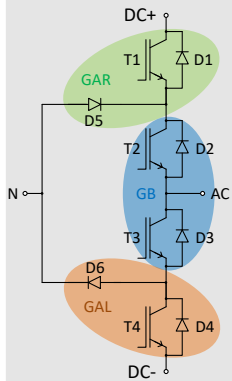
3L NPC Setup with SEMITRANS

Setup A:GAR



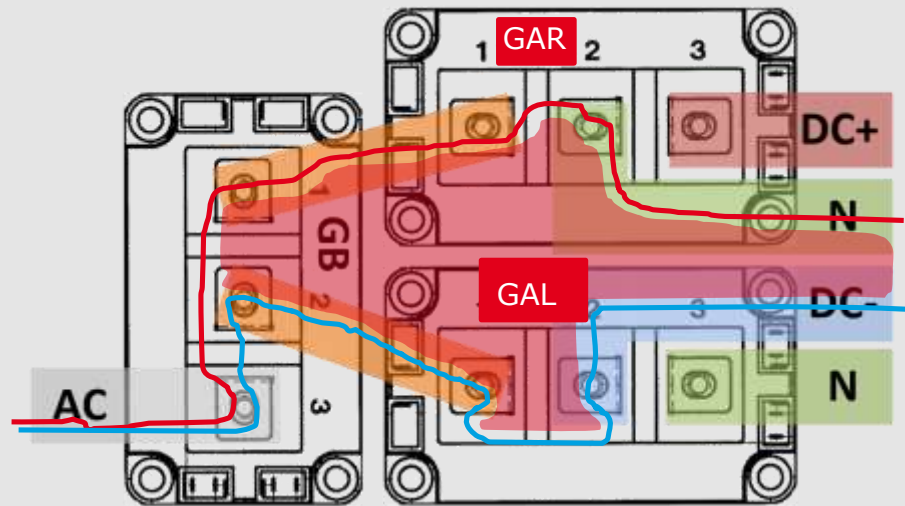
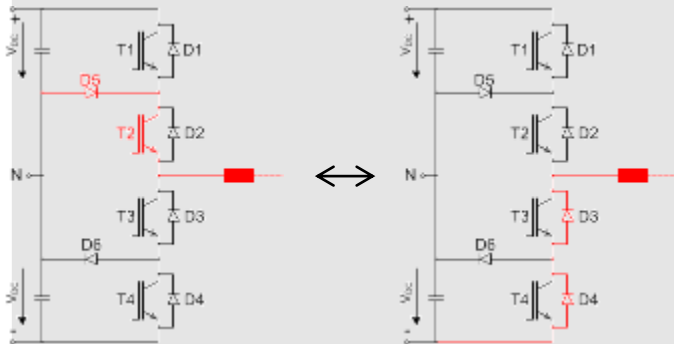
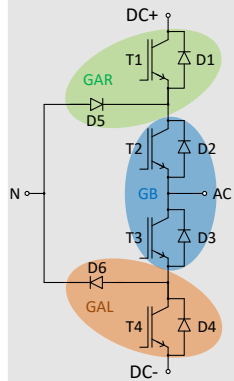
SEMITRANS GAR, GB and GAL: Setup A

Setup A: current paths and short commutation loop $T1/T2 \Leftrightarrow D5/T2$



SEMITRANS GAR, GB and GAL: Setup A

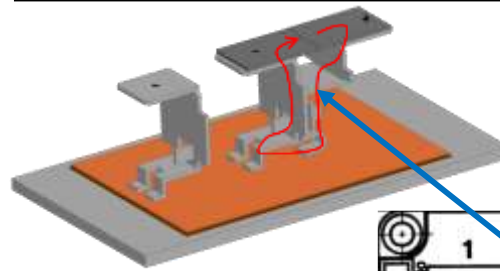
Setup A: current paths and long commutation loop D5/T2 $\leftrightarrow$ D3/D4



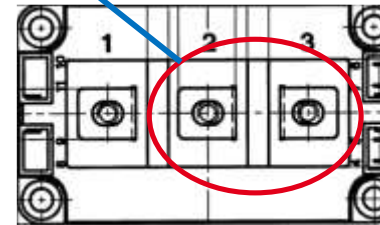
SEMITRANS Stray Inductance – Competitor Stray Inductance

Setup A stray inductances:

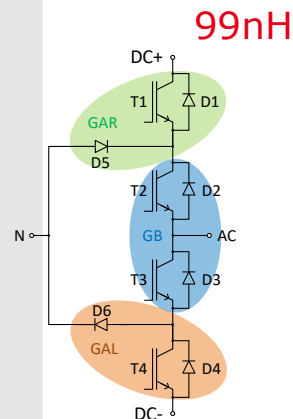
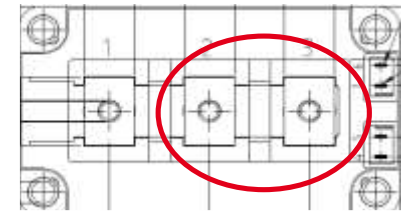
- **Short commutation path: 12nH**
- **Long commutation path across module boundaries: 99nH**
- **Reduction to 60nH with laminated busbar possible**



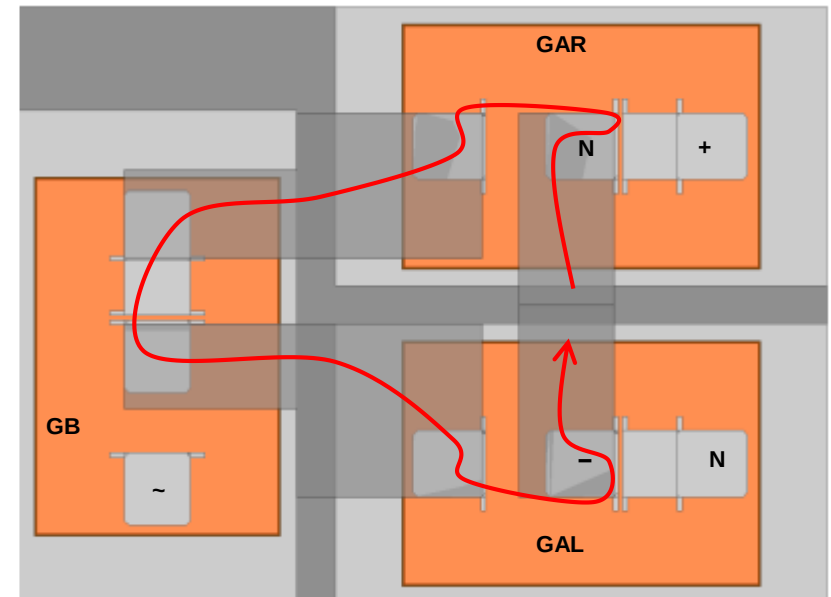
12nH



Competitor above 15nH
Check terminal design



99nH



Packaging Technology in different Application



Introduction of solar & ESS

2-level & 3-level features

3-level for ESS & Solar (ANPC)

3-level Central Converter Design

3-level Commutation Difficulties

Summery

Summery Solar & ESS



- Cost pressure is getting higher and higher
- Reliability is a MUST
- Solar & ESS Converter as one unit, power factor -1
- Power factor -1 means – selection of the right diode inside the power module to improve efficiency
- Air cooled System are common
- Consider environment and creepage distance



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